



FLAGSHIP FOR PHOTONICS RESEARCH AND INNOVATION (PREIN)

Optics and Photonics Days 2024
May 28, Helsinki



Program

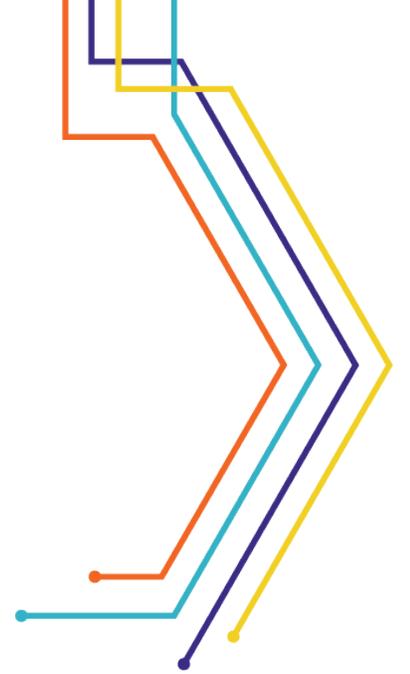
15:00 - 15:30 **PREIN summary of 2023 activities**

15:30 - 16:15 **Pitch sessions of PREIN internal research projects**

16:15 - 16:30 **Research highlights: PREIN Research Council of Finland Proof of Concept projects**

16:30 - 17:15 **Innovative ecosystem for doctoral education in Photonics (I-DEEP)**

17:15 - 18:00 **Panel discussion**



In the past 10 years Finland has established an extensive ecosystem for Photonics RDI

RESEARCH NETWORK

Flagship for Photonics Research and Innovation (PREIN)
Research excellence



INFRA. NETWORK

Finnish National Infrastructure for Light-Based Technologies (FINNLIGHT)
Open-access infrastructure covering full innovation chain



INDUSTRY NETWORK

Photonics Finland
National networking platform for business & industry



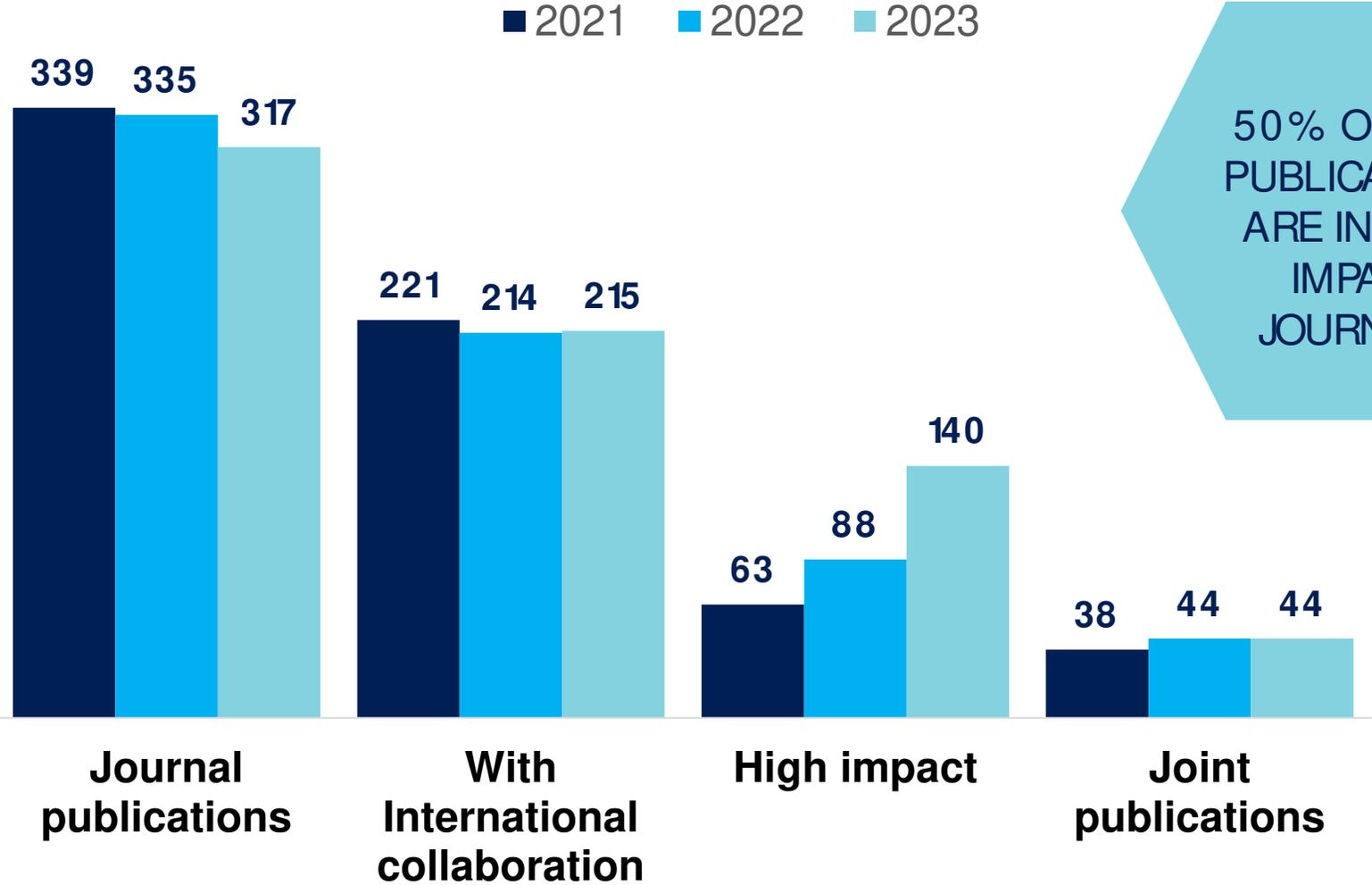
EDUCATION NETWORK

Innovative Doctoral Education Ecosystem for Photonics (I-DEEP)
Doctoral pilot program to support business & industry



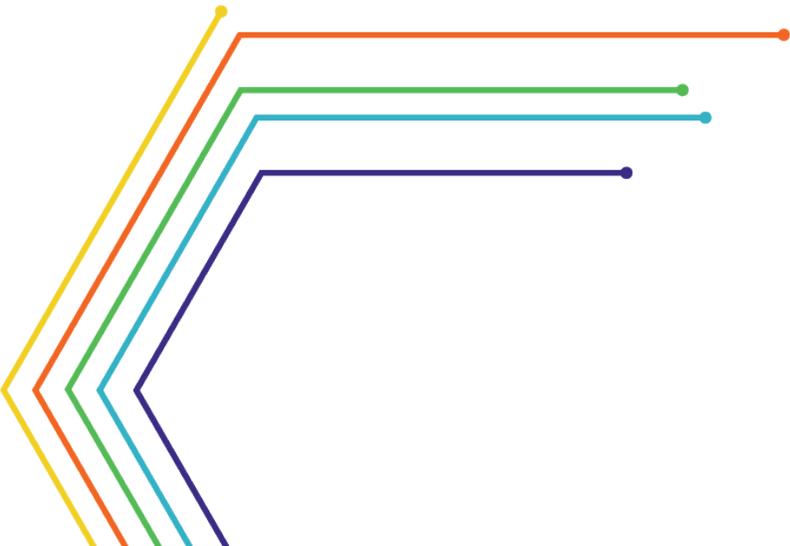


PREIN Ecosystem Strengthens Research Quality



50% OF OUR PUBLICATIONS ARE IN HIGH IMPACT JOURNALS

80% OF OUR PUBLICATIONS ARE OPEN ACCESS



PREIN Ecosystem Strengthens Research Quality

STAFF



+50%
(500+)

DIVERSITY



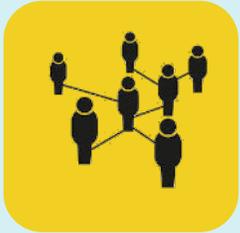
29% FEMALE
46% FOREIGNERS

EDUCATION



315 MSc and 118 PhD
PRODUCED

NETWORKING



2 NETWORKING
EVENTS PER
MONTH

STARTUPS

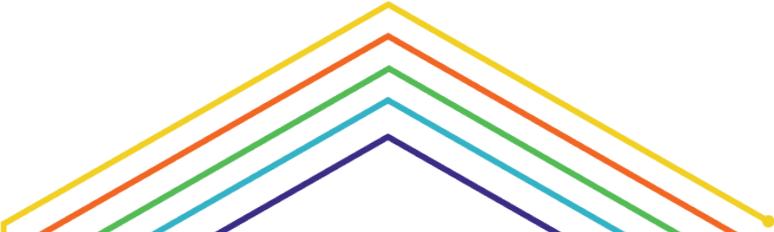


7 NEW
STARTUPS

PATENTS



62 PATENT
APPLICATIONS



Collaboration & Dissemination

- Thematic events
- Internal events for researchers and students
- Outreach events



PREIN workshop

Light for families

Students visit to Aalto



Collaboration & Dissemination

- Public people
- Media
- Arts



Valon voimalla - Fotoniikka on puhdasta energiaa!



Arts

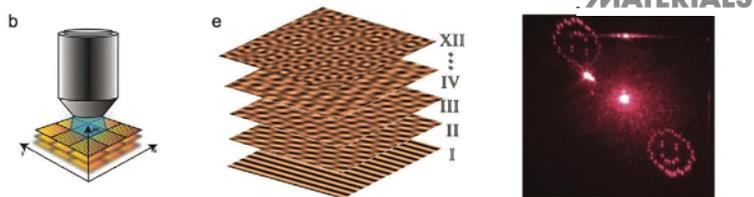


Media

Scientific Highlights

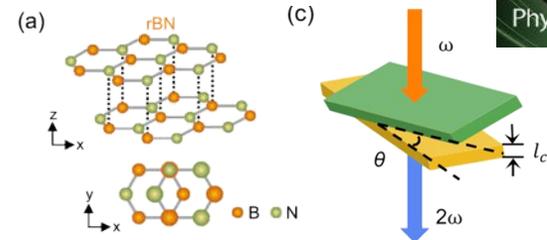
Material Science

Complex Fourier Surfaces by Superposition of Multiple Gratings on Azobenzene Thin Films



ADVANCED OPTICAL MATERIALS

Twist Phase Matching in Two-Dimensional Materials

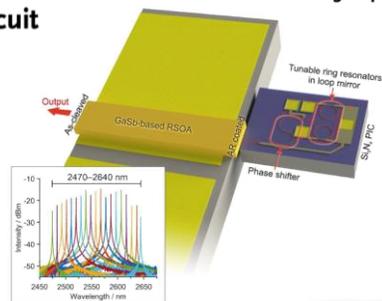


Physical Review Letters
moving physics forward

Light Sources

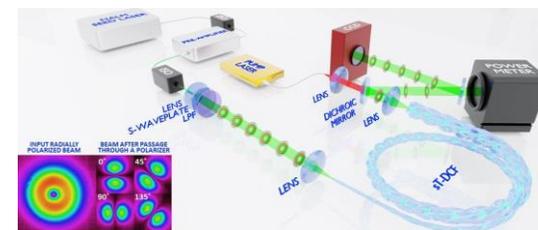
Widely Tunable (2.47–2.64 μm) Hybrid Laser Based on GaSb/GaInAsSb Quantum-Wells and a Low-Loss Si₃N₄ Photonic Integrated Circuit

LASER & PHOTONICS REVIEWS



Double-clad ytterbium-doped tapered fiber with circular birefringence as a gain medium for structured light

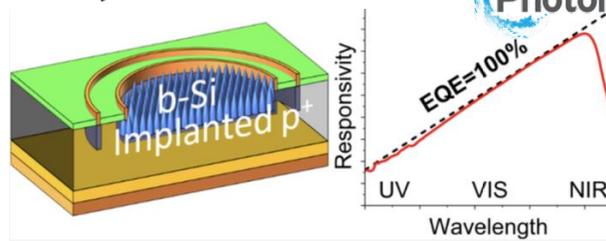
Optics Letters



Solar Energy

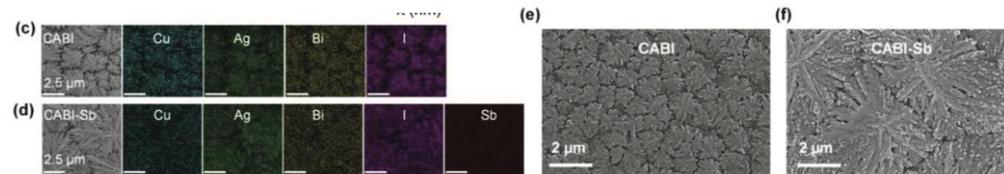
Boron-Implanted Black Silicon Photodiode with Close-to-Ideal Responsivity from 200 to 1000 nm

ACS Photonics



Antimony-Bismuth Alloying: The Key to a Major Boost in the Efficiency of Lead-Free Perovskite-Inspired Photovoltaics

NANO · MICRO small



Increasing the Impact of Our Research

COLLABORATION

Joint projects coordinated by postdocs in each partner institution

3 projects funded on solar cells, environmental sensing, and quantum photonics

PROOF-OF-CONCEPT

Demonstrating the feasibility of ideas and utilise research results

3 projects funded on integrated laser sources, nanolasers, and detection of black plastics

DOCTORAL TRAINING

Innovative approaches to accelerate graduation time without compromising quality

New national innovative doctoral education ecosystem for Photonics

ROADMAP

Long-term vision of our research and target areas where we envision our technology can have an impact

New roadmap for 2024-2027+ with technologies in sensing, imaging, light generation & solar energy

PREIN 2020-2024 Roadmap

	Smart sensors		Integrated Photonics		Light sources			Photovoltaic		
	Biosensors	Gas sensing	Components	LIDAR	Mid-IR sources		Nanoscale	III-V solar cells	Perovskites	c-Si
2020	Printable microfluidistic platform for bioaffinity assays	Broadband photoacoustic gas analyser for 2.5 – 3.5 μm using super continuum source	Hybrid III-V-on-silicon-on-insulator lasers	Large waveguide arrays and printed 3D lenses for >10m working distance	Supercontinuum Watt-level sub nanosecond seed laser beyond 2.3 μm	Tunable photonic integrated circuit lasers GaSb-based gain for 2.7 μm	III-V QDs for 1.5 μm and 2D materials μm	Compact concentrator photovoltaic proto panel 28% eff. and highly eff. 4J 5Cs	Design and synthesis of non-toxic lead-free perovskites	Passivated Emitter and Rear Cell and/or Tunnel Oxide Passivated Contact b-Si solar cells
2021	Fluorescence readout with single photon Fluorescence readout with single photon detectors (SPAD)	Miniaturized interferometer for portable photoacoustic broadband gas sensor	100 GHz on-chip optical modulators	Tunable light source based on hybrid III-V integration on 3 μm silicon-on-insulator	Fiber or waveguide integrated architecture	Low-loss silicon photonics echelle gratings and ring-resonators at 2-3 μm	High-speed few-photons plasmonic nanolasers at cryogenic temperature	New 5J and 6J solar cells for ~50% eff.	Earth-abundant photovoltaic components and green-solvent processing	Extending to possible tandem cell technology
2022	Integration of printable microfluidistic sensor platform with Fluorescence readout with single photon detector -based readout for ultra-sensitive and selective biosensing	Utilizing of tunable photonic integrated circuit lasers for broadband gas sensing	100 nm bandwidth on-chip circulator for photonic integrated circuits	Waveguide gratings and phase modulators for fast power-efficient 3D scanning	Machine-learning control	Hybrid integration of gain chips and tuning silicon photonics elements	Single particle excitation based on plasmonic cavity with broad tuning	Compact concentrator photovoltaic panels with >40% eff.	Environmental and mechanical stability of green photovoltaic components	Upscaling the selected b-Si solar cell technology (possibly with external partners)
2023	Time-gated Fluorescence readout with single photon detector array for Raman sensing on the microfluidistic platform	Miniaturized gas sensor based on a tunable photonic integrated circuit laser at 2-3 μm wavelength	10 Tbps hybrid transceiver	Integrated LIDAR module on a single chip	Compact on demand supercontinuum in 2-8 μm	Wavelength programable integrated laser in 2-3 μm	Efficient single particle excitation and high-speed nanolasers with ultra-low energy/bit	Compact panels integrated with dense matrix micro-concentrator photovoltaic III-V chips	Device engineering to maximize the performance of green perovskite photovoltaics	Panel fabrication and outdoor testing in collaboration with industry
2024										

ABOUT 75% OF OBJECTIVES REACHED

NEW RDI OBJECTIVES FOR NEXT 4 YEARS

TARGETS IN APPLICATION AREAS RATHER THAN COMPONENT LEVEL

Life science ICT Autonomous vehicles and mobile devices Environmental monitoring and healthcare Quantum cryptography and superconducting logic Compact efficient photovoltaic panels and clean energy

	Sensing			Imaging			Light Generation & Manipulation			Solar Energy		
2024	Biosensing New plasmonic substrates enabling digital	Environmental Sensing Soil-carbon analysis	Industrial Sensing Mineral micro-spectroscopy and mineral mapping	Advanced Microscopy THz super-resolution microscopy	LIDAR FMCW Lidar chip with integrated 1D OPA	Hyperspectral Imaging THz & IR hyperspectral imagers	Quantum Light QD material for telecom C-L band	Tunable Active Devices PIC laser for 3 um	Ultrafast Lasers Pulsed plasmonic nanolasers	New Materials & Concepts Lead-free perovskite PV active layers in flexible modules at 50% FF & 2% PCE	Perovskites Integrated flexible perovskite PV modules	Crystalline Silicon Utilize up-conversion in PERC solar cells
2025	High-Q metasurfaces Vis-NIR Spectrometry in wearable devices	Microplastics from open water	Bioprocess control using sensor fusion	High-transmission extra-long field-of-view microscope	FMCW Lidar chip with 2D beam steering	On-chip hyperspectral imager	Deterministic telecom wavelength single & entangled photon sources	On-chip isolators & circulators On-chip polarization management	Fully-integrated on-chip laser with 1 W av. power	Advanced integrated PV for low power applications (PCE>20%)	Fully solution processed perovskite PV with over 10% PCE	Surface passivation & charge transfer for photo-electro-chemical cells
2026	Record-high SERS Quantum biosensing of temperature, pH, ROS in living cells	Few-ppb atmospheric gas sensors	In-line microplastics monitoring	Novel fluorophores & markers	Sub-wavelength-pitch waveguide arrays using HOM	Advanced post-processing using AI & ML	High-Q cavities based on metamaterials	1D/2D materials-based lasers	Fiber-based 350-800 nm structured light Fiber-based optical computing	PV module made from biodegradable materials	Device engineering to reach 5% PCE for green perovskite PVs	Tandem perovskite solar cells with nanostructure to reduce reflective losses
2027	Single molecule detection with plasmonic substrates			Quantum super-resolution fluorescence microscope	On-chip 3D LIDAR		Chip-based quantum operation using photon pairs	On-chip laser with 100+ nm tuning range	GHz pulsed PIC laser for triggering quantum emission	Perovskite-inspired materials for self-powered photodetectors	R2R processed flexible perovskite PV	
Environmental monitoring and healthcare			Life science	Autonomous vehicles and mobile devices		Safety & Security	Quantum technologies	ICT	Clean energy & sustainability			

Comprehensive Summary in our 2023 Annual Report



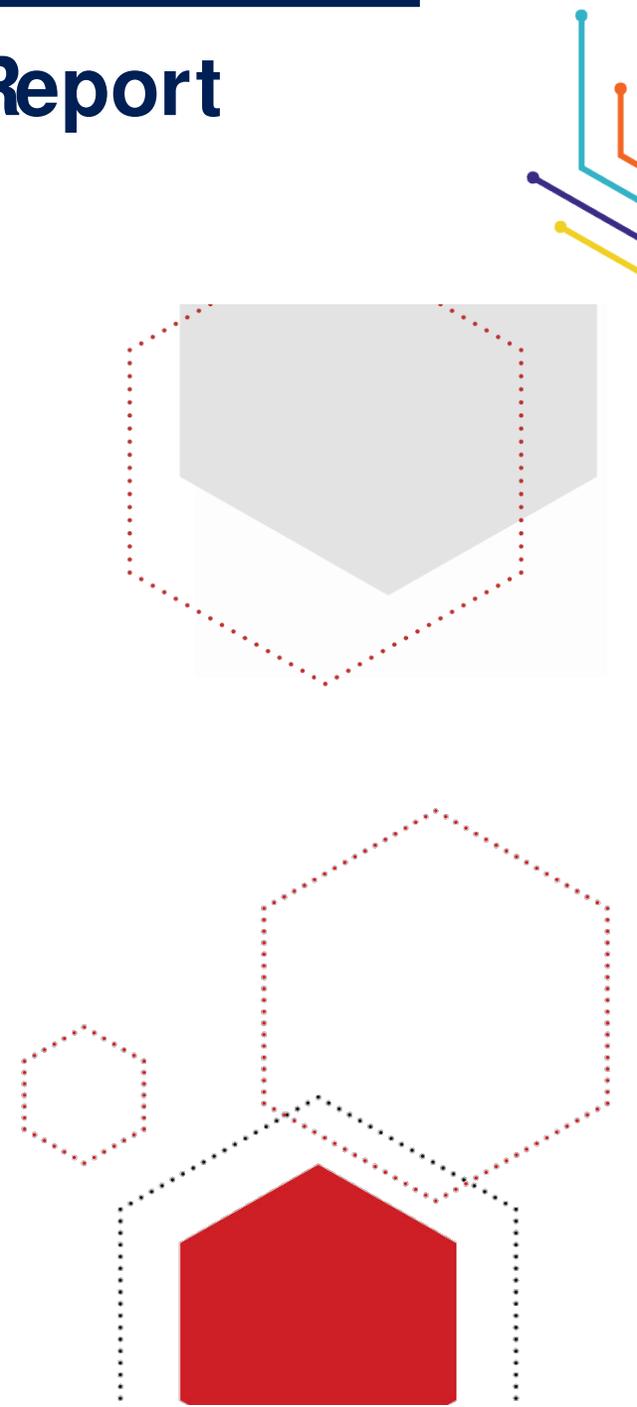
PREiN

Flagship for Photonics Research
and Innovation (PREIN)

Annual Report 2023

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Advanced Infrastructure Supporting RDI in Light-based Technologies



Entire photonics value chain: design, fabrication, integration, characterization



Open to external researchers and companies



Finnlight.fi

*National Roadmap
Infrastructure*



Research Council
of Finland

Advanced Infrastructure Supporting RDI in Light-based Technologies

National roadmap status: 2021-2024

Applied to renew status for 2025-2029

Successful in 2023 funding call (3.8 M€) to expand our capabilities

*National Roadmap
Infrastructure*



Finnlight.fi



How to Use our Infrastructure Network?



Finnlight ▾ Design ▾ Fabrication ▾ Inteartion ▾ Characterization ▾ How to use Contact

Micro- and Nanopatterning

Material processing

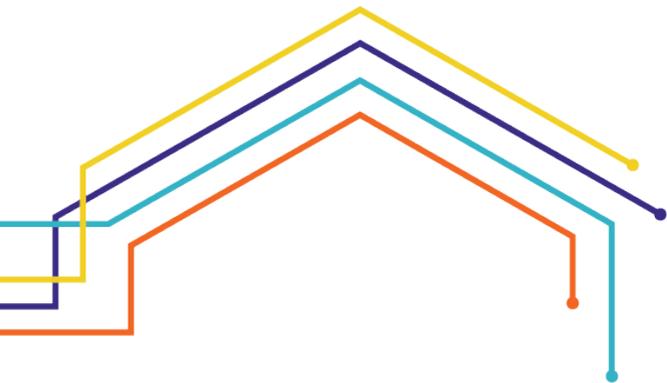
Thin film deposition and epitaxy

FinnLight – Finnish Research Infrastructure on Light-Based Technologies

FinnLight provides a comprehensive combination of technologies covering all classes of photonics materials as well as full-scale process lines for device fabrication and assembly.

About FinnLight

finnlight.fi



FABRICATION

Micro- and Nanopatterning

Micro- and nanolithography is a key technology in manufacturing of integrated circuits and microchips that allows for creating patterns with a feature size from nanometer up to millimeter scale. Lithography techniques can be divided into two types: masked lithography and maskless lithography. Masked lithography such as photolithography and nanoimprint lithography makes use of masks to transfer patterns over a large area simultaneously making the process cost-effective. Maskless lithography such as electron beam lithography and laser writing enable arbitrary patterns with high-resolution and a minimum feature size as small as a few nanometers.

Micro- and Nanopatterning

-- Select location --

-- Select wavelength --

Filter



Fabrication > Micro- and Nanopatterning

Electron Beam Lithography, EBL

We offer the entire fabrication chain or a portion, such as e-beam patterning, according to the customer's design.

More info



Fabrication > Micro- and Nanopatterning

Nanoimprint Lithography, NIL

We offer both master element fabrication and nanoimprint lithography services.

More info



Fabrication > Micro- and Nanopatterning

Spin coating

Spin coating is a method to apply a uniform film onto a solid surface by using centrifugal force and requires a liquid-vapor interface.

More info



Fabrication > Micro- and Nanopatterning

Digital holographic microscopy and interference lithography

Digital holographic microscopy (DHM) is a quantitative phase imaging technique, where both the amplitude and phase of light interacting with a sample are measured. The phase contains information on the height and refractive index variations on a sample. In the...

More info



Fabrication > Micro- and Nanopatterning

Optical lithography

Top side UV-lithography, Bottom side UV-lithography, Micro and nanoimprint lithography (SMILE), UV-bonding

More info

How to Use our Infrastructure Network?



Finnlight ▾ Design ▾ Fabrication ▾ Inteartion ▾ Characterization ▾ How to use Contact

- Micro- and Nanopatterning
- Material processing
- Thin film deposition and epitaxy

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About FinnLight

Send an enquiry
 *** indicates required fields

Select recipient for your enquiry:
 Jukka Viheriälä(Tampere)

Name*

Email*

Phone*

Organization*

Your message*

Submit

Imprint lithography
 Imprint lithography utilizes large thin UV-transparent glass or PET foils to act as a working stamp. Separate tool is used to replicate on top of this foil nano or micropattern from template/master wafer. User loads foil into the system and a substrate with UV-curable polymer. Aligner brings patterned stamp surface into contact with UV-polymer and applies force to evacuate gas trapped between two surfaces. Once contact is achieved UV-lamp of the tool cures UV-polymer and tool rips stamp from cured polymer.

UV-bonding
 Tool is used to bring two substrates in contact (and align them). If interface between substrates is covered with UV-curable polymer it is possible to cure expose through top substrate and cure UV-polymer.

Nominal Specifications
 Substrate max thickness 1.5 mm in vacuum contact and 7 mm in other modes
 Illumination uniformity +/- 2.5%
 Light source: UV-LED, 3 individually adjustable lines

- 365 nm (i-line)
- 405 nm (h-line)
- 435 nm (g-line)

Two exposure optics settings:

- For large gap between mask and substrate
- For large resolution

Alignment accuracy:

- Top side < 0.5 µm (0.25 µm with auto-align software)
- Bottom side < 1 µm
- Imprint < 2 µm

Fabrication > Micro- and Nanopatterning Optical lithography



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Micro- and Nanopatterning -- Select location -- -- Select wavelength -- Filter

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More info

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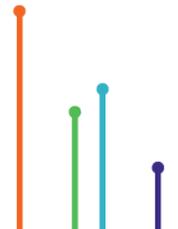
More info

Optical lithography

Top side UV-lithography, Bottom side UV-lithography, Micro and nanoimprint lithography (SMILE), UV-bonding

More info

Find the service you need & click to contact form



How to Use our Infrastructure Network?



Finnlight ▾ Design ▾ Fabrication ▾ Integration ▾ Characterization ▾ How to use ▾ Contact

Micro- and Nanopatterning

Material processing

Thin film deposition and epitaxy

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About FinnLight

**Manager position open next week
(located at Tampere University)**

Fabrication > Micro- and Nanopatterning



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Micro- and Nanopatterning

-- Select location --

-- Select wavelength --

Filter



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More info



Fabrication > Micro- and Nanopatterning

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More info

Find the service you need & click to contact form



Company collaboration

- Exhibitions
- PREIN meets X
- Business delegations
- Investments



**Business Finland's
photonics business
delegation in Japan**



**Investing in Photonics and
Microelectronics**



Finland Pavillion at Photonics West

Education Campaign: Photonics Explorer Kit



 **Photonics Finland**

- Donate 1 Kit to a school,
PREIN/ Photonics Finland will donate 2 more!
- Over 100 optical components
- Recreational activity to interest children in science


PREIN
Photonics Research
and Innovation

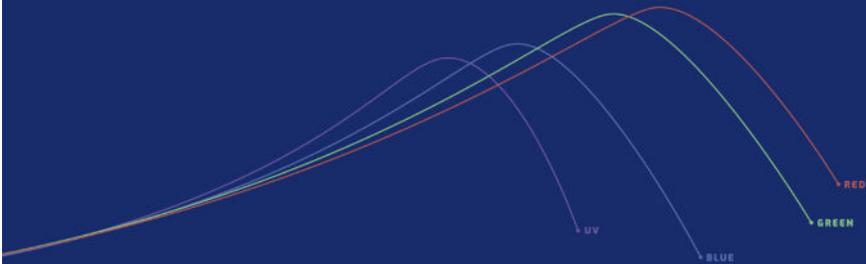
Useful Resources

prein.fi



PREiN

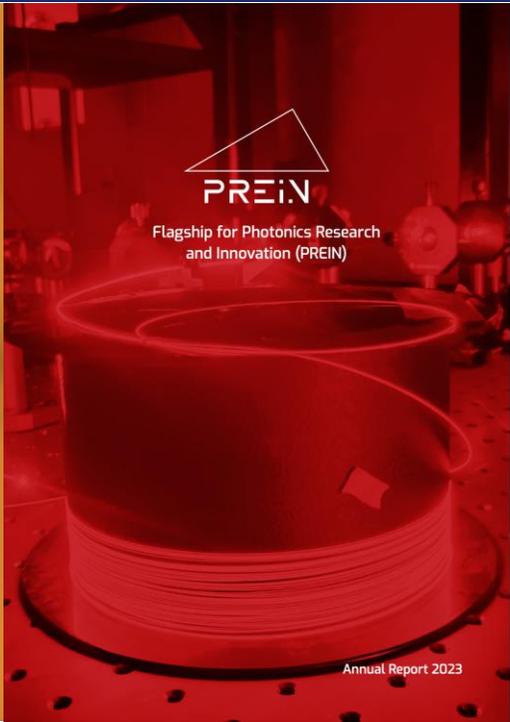
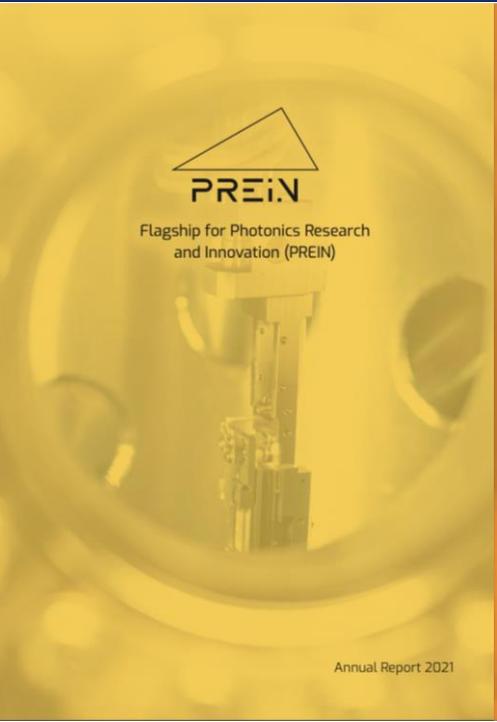
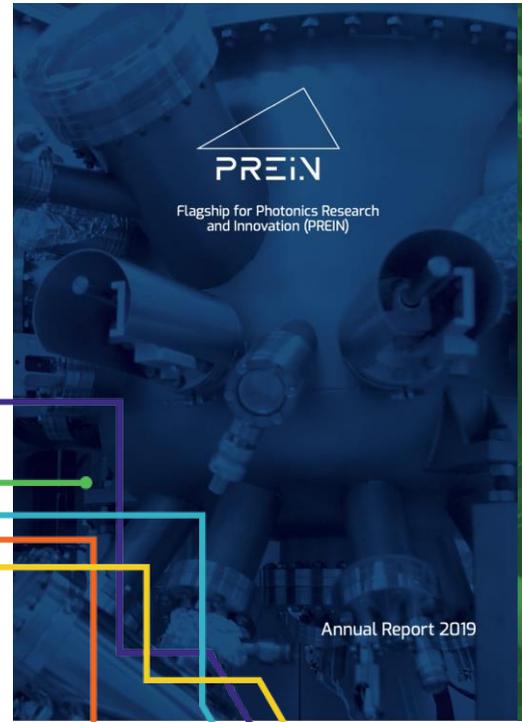
- ABOUT ▾
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- RESEARCH ▾
- STUDIES ▾
- I-DEEP ▾
- OUTREACH ▾
- FOR INDUSTRY ▾
- CONTACT US



PHOTONICS – THE SCIENCE OF LIGHT

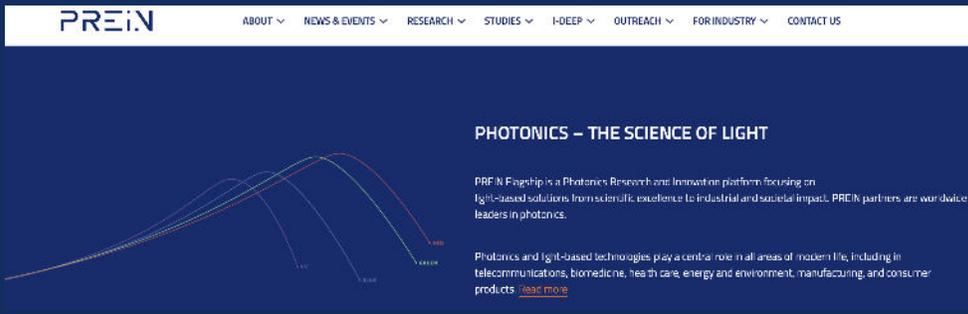
PREIN Flagship is a Photonics Research and Innovation platform focusing on light-based solutions from scientific excellence to industrial and societal impact. PREIN partners are worldwide leaders in photonics.

Photonics and light-based technologies play a central role in all areas of modern life, including in telecommunications, biomedicine, health care, energy and environment, manufacturing, and consumer products. [Read more](#)



Websites

Prein.fi



Finnlight.fi

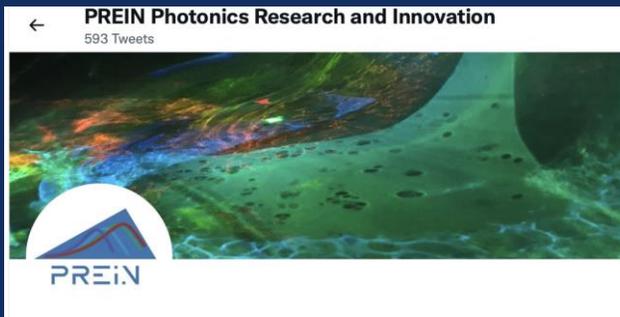


Channels

LinkedIn



X/Twitter



Newsletter



PREIN Team

Goëry Genty
Director



Jyrki Saarinen
Vice-director



Tea Vellamo
Admin. coordinator



Juha Purmonen
Impact manager

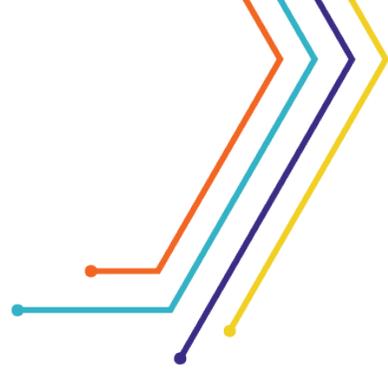


Kristiina Pispala
Communication specialist



Raili Termälä
Impact specialist

Program



15:00 - 15:30 **PREIN summary of 2023 activities**

Goëry Genty, PREIN Director, Tampere University

15:30 - 16:15 **Pitch sessions of PREIN internal research projects**

Thomas Kraft (VTT), Perovskite-inspired indoor photovoltaics for sustainable Internet-of-Things

Juha Toivonen (TAU), Multi-sensory environmental sensing for enhanced sensitivity and selectivity

George Thomas (VTT), and Vladimir Kornienko (Aalto), Structured Quantum Photonics with Geometric Phases

and Integrated Circuits

16:15 - 16:30 **Research highlights: PREIN Research Council of Finland Proof of Concept projects**

Mircea Guina (TAU), Integrated pulsed lasers driving industrial scaling of quantum technologies (IntegrateQT)

Eduardo Maia Paiva (VTT), Broadband active hyperspectral sensing for black plastic

16:30 - 17:15 **Innovative ecosystem for doctoral education in Photonics (I-DEEP)**

Sari Multala, Opening words (video)

Goëry Genty, presentation of I-DEEP

Heikki Holmberg, Industry vision

17:15 - 18:00 **Panel discussion**

Jyrki Saarinen, PREIN/UEF

Suvi-Tuuli Akkanen, PhD researcher Aalto University

Leena Pöntynen, Technology Industries

Heikki Holmberg, Research and Development Director, Okmetic Oy

Jyri Hämäläinen, Vice President of Research, Aalto University



ACADEMY OF FINLAND



FLAGSHIP PROGRAMME



Tampere
University



A!
Aalto University



UNIVERSITY OF
EASTERN FINLAND



VTT



VTT

Perovskite-inspired Indoor Photovoltaics for Sustainable Internet-of-Things PINT

Thomas Kraft, PhD
Senior Scientist, Project Manager
VTT

7.6.2024

VTT – beyond the obvious

PREIN

thomas.kraft@vtt.fi

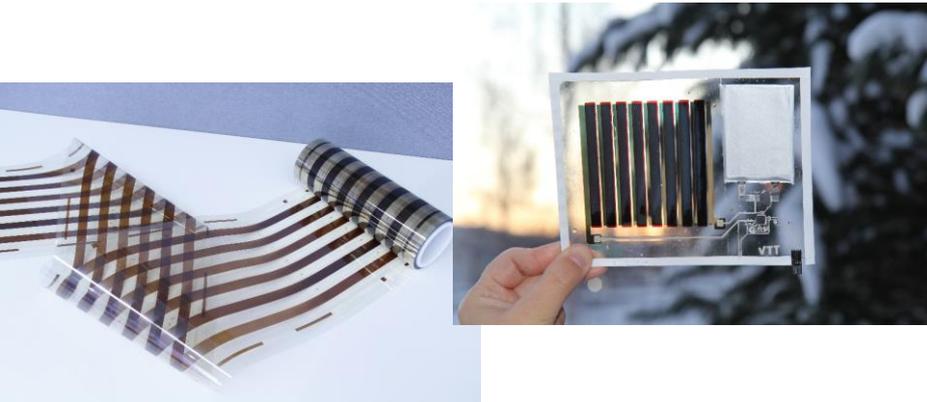


PREIN

Photonics Research
and Innovation

Perovskite-inspired indoor photovoltaics for sustainable Internet-of-Things

- Powering the internet-of-things:
 - Perovskite solar cells are efficient photovoltaic technology that can solve this issue leading to self-powered and wireless devices.
- The aim is to develop lead-free perovskite-inspired materials (**PIMs**) for indoor photovoltaic (**IPV**) applications.



7.6.2024

VTT – beyond the obvious
PREIN thomas.kraft@vtt.fi



Molecular
Modeling
Mikko
Linnolahti

Hybrid
Solar Cells
Paola Vivo



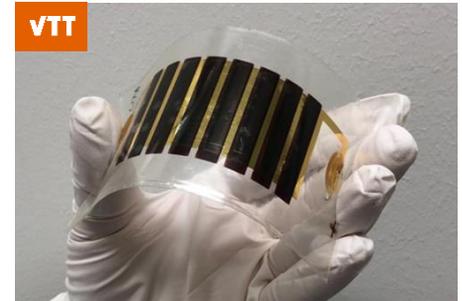
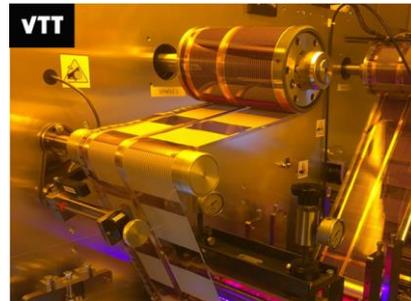
Multifunctional
Materials Design
Jaana
Vapaavuori



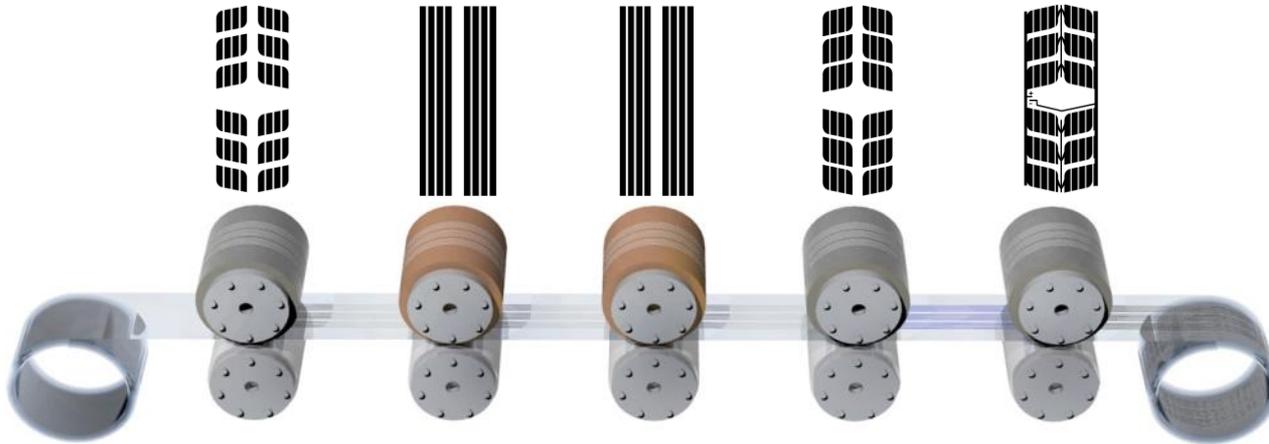
VTT

Printed
Materials
Systems
Thomas Kraft

Device Manufacturing

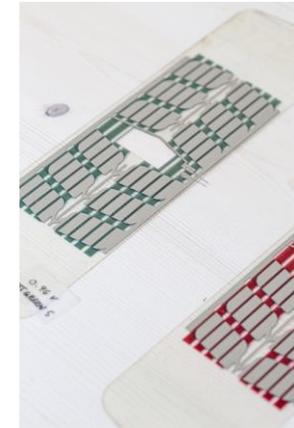


Multilayer processing



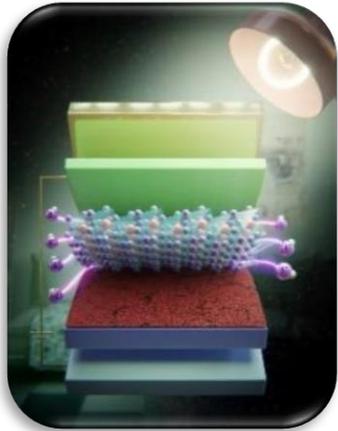
Spin, slot die, blade, bar coating.

Gravure, flexo, screen printing.

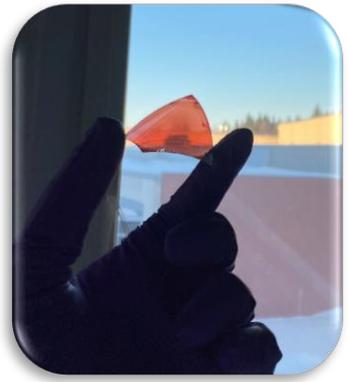


Encapsulation, lamination

PINT Project



Indoor PIM for PV
-lead-free-



Develop a new family of lead-free PIMs

Establish an ad-hoc processing method

Sustainable low-cost manufacturing of flexible PIM-based indoor PVs

Investigate stability of indoor PVs



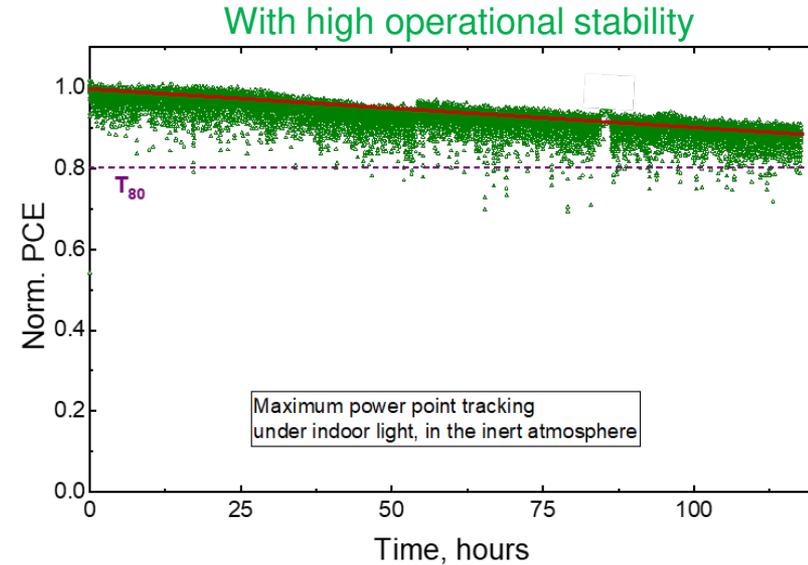
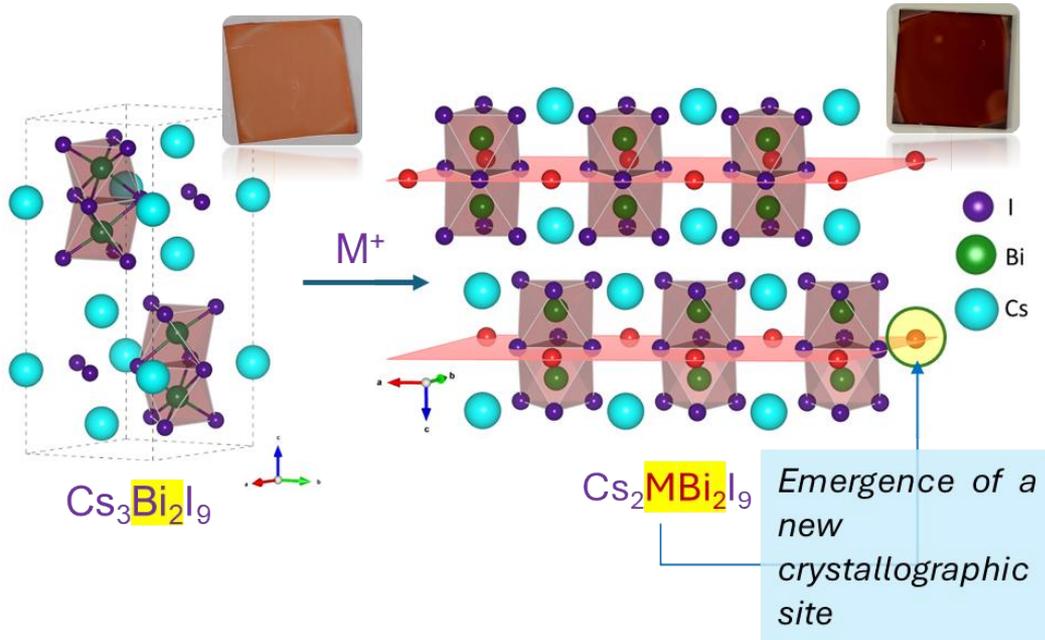
- ✓ Developing a new family of lead-free PIMs for indoor photovoltaics
 - ✓ **Molecular modeling** aims to aid in developing a new family of lead-free perovskite-inspired materials
 - ✓ Initiated by assessing the effects of polymorphism on the **predicted electronic structure and stability of perovskites**
- ✓ Material (structural, spectroscopic) characterization
- ✓ Device performance assessment, including operational stability

A new Bismuth perovskite-inspired material for IPV

0D→2D: A-site cation engineering facilitate the electronic dimensionality **tuning for improved carrier transfer.**

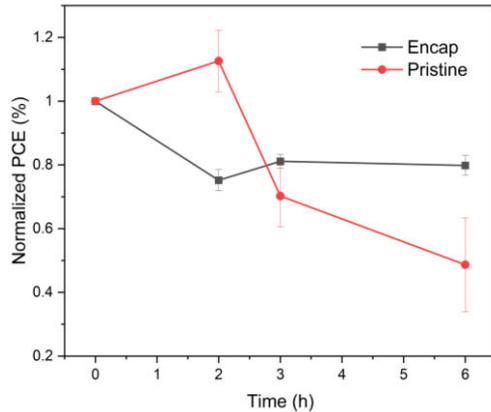
Bandgap reduction: A-site cation engineering **lowers the bandgap** for enhanced indoor light absorption.

Promising IPV performance: IPV efficiency of **~5%** has been achieved for $\text{Cs}_2\text{MBi}_2\text{I}_9$.

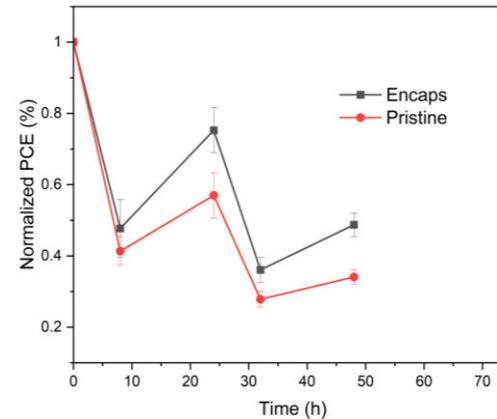


Understanding of CABI solar cell's durability to environmental factors ($\text{Cu}_2\text{AgBiI}_6$)

- CABI less sensitive to moisture compared to lead-based perovskite solar cells
- Photo stability is a challenge; light management has potential to improve this



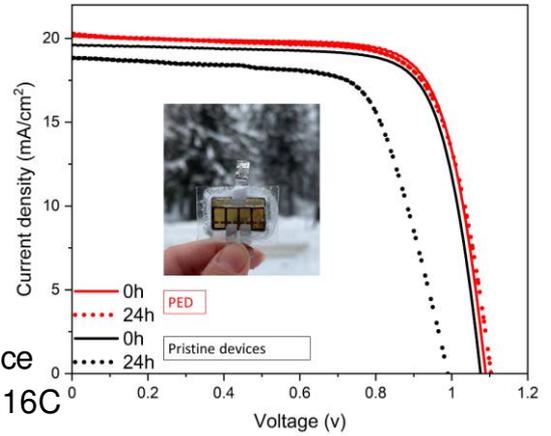
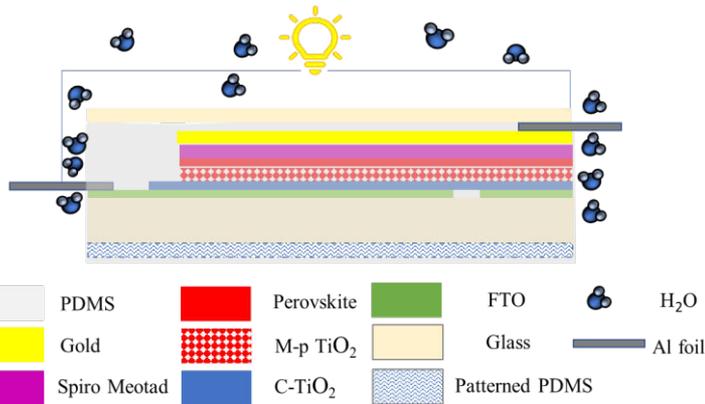
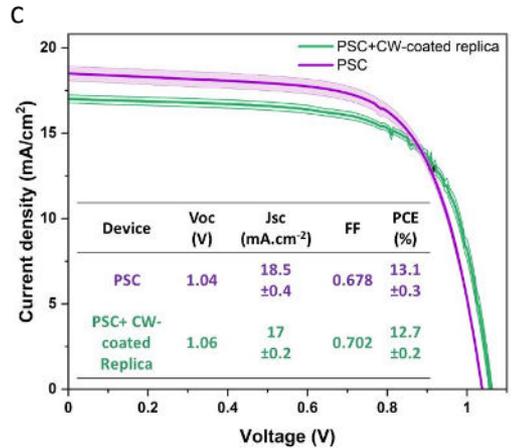
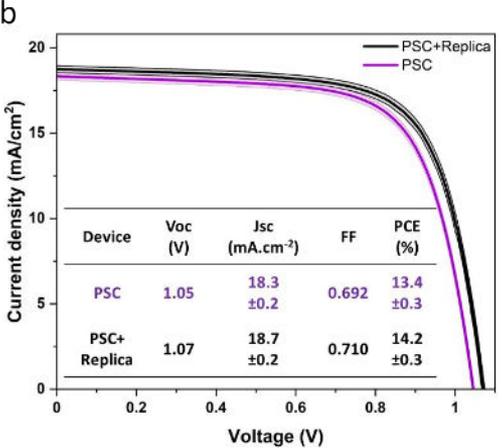
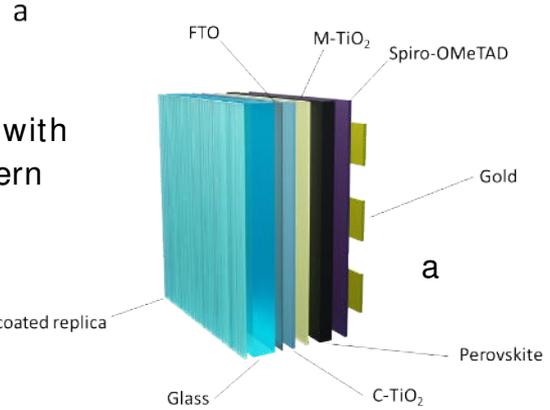
Encapsulated and pristine devices exposed to 90% RH



Encapsulated and pristine devices under cycles of 8 hours under 1 sun and 16 hours resting in the dark in the ambient condition

In-situ encapsulation and surface patterning

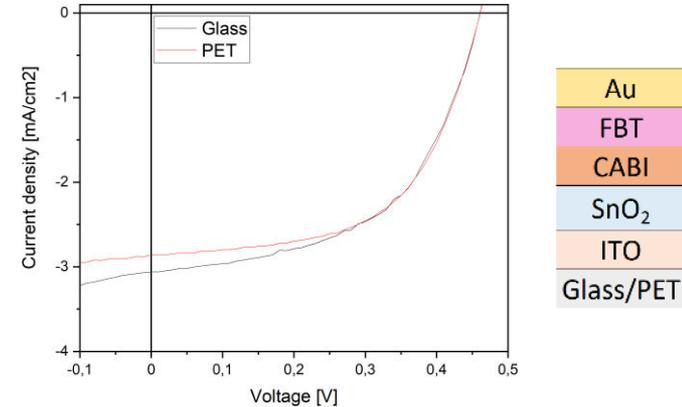
8% PCE increase with surface leaf pattern



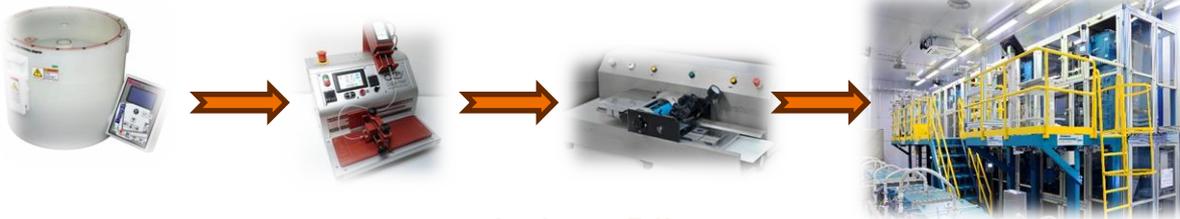
Performance testing at -16C

Upscaling

- **Motivation**
 - Volume deposition methods for lead-free perovskite-inspired material ($\text{Cu}_2\text{AgBiI}_6$) → Aiming for roll-to-roll applicable techniques
- **Key Results**
 - Ambient solution processing of lead-free perovskite-inspired material ($\text{Cu}_2\text{AgBiI}_6$) on flexible substrate (*manuscript under preparation*)
 - Investigation performance and thin-film morphology

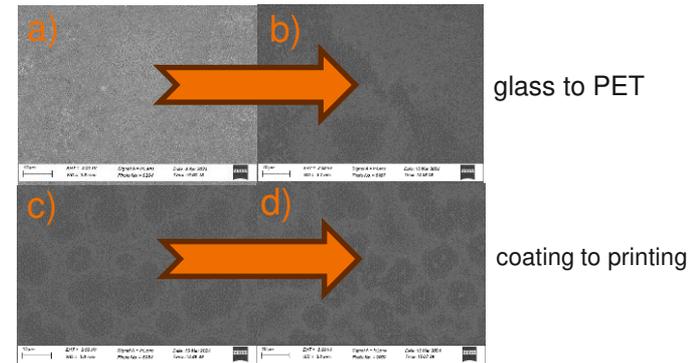


IV-figures from the devices made on glass and PET.



Lab to Pilot

Similar performance going to flexible substrates



Scanning electron microscope images from $\text{Cu}_2\text{AgBiI}_6$ films processed via spin coating on glass (a) and PET (b), and slot-die coating on PET (c), and gravure printing on PET (d).

PINT outcome

- New class of lead-free perovskite inspired materials used in IPV
- Sustainable encapsulation and light management approaches
- Volume compatible upscaling options on flexible materials

Technology Partnerships with VTT

- Printed & Hybrid Electronics Infrastructure
- Prototyping & Process development
- Machine Sourcing & Ramp-Up
- Technology Consultation

Facilities video:

<https://www.youtube.com/watch?v=sh62l9fFXgl>

Thank you to my colleagues at VTT and all partners!

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www.printocent.net

- Molecular modeling aims to aid in developing a new family of lead-free perovskite-inspired materials
- Mid-term goal is to assess software capabilities and demonstrate how input structure impacts material properties of interest
- Initiated by assessing the effects of polymorphism on the predicted electronic structure and stability of perovskites
- Perovskites are chosen due to abundant experimental data and readily available tools for building different polymorph structures

Convex Hull Analysis: Online databases allow reliable determination of thermodynamic stability for a given composition

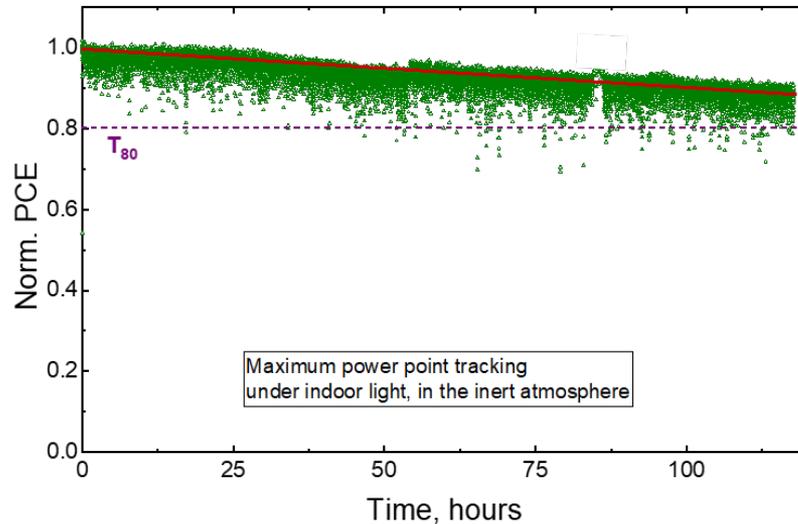
Polymorph Stability: Assessing polymorph stability accurately requires employing higher-level theories

Energy-Band Gap Correlation: An inverse correlation between total energy and band gap has been observed between polymorphs with same composition

Spin-Orbit Coupling: Exclude spin-orbit coupling for more accurate electronic structure calculations

Pnma Polymorphs: Using Pnma space group polymorphs appears to improve band gap accuracy over the ideal cubic perovskite structure

Project-II: A mixed-metal chalcogenide-halide material for stable IPV performance



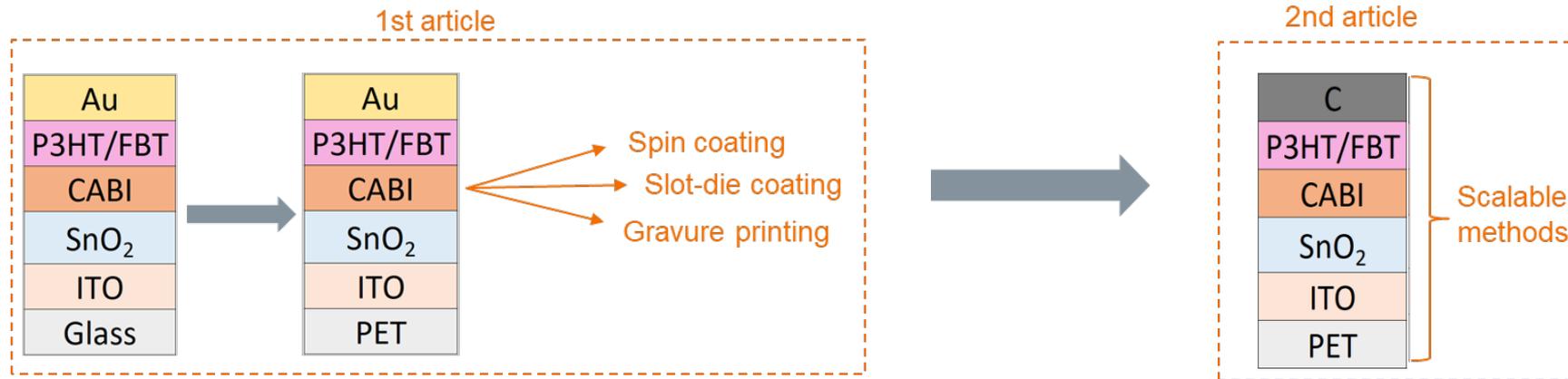
A pnictogen-based perovskite-inspired material that contains both chalcogenide (for stability) and halide (for defect tolerance) ions has been synthesized. $\text{Cs}_2\text{MBi}_2\text{I}_9$

Defect tolerance: A low Urbach energy of ~ 35 meV suggests a good defect tolerance.

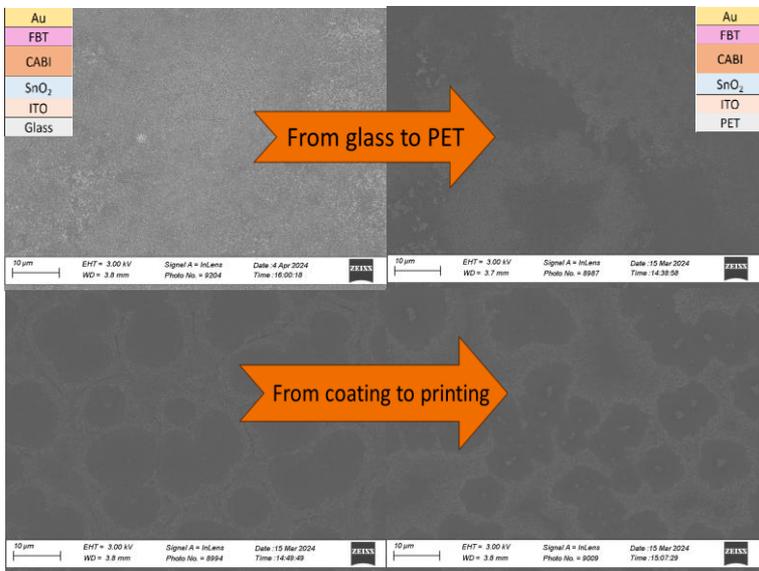
High IPV operational stability: A stable performance for more than 100 hours has been achieved.

Target

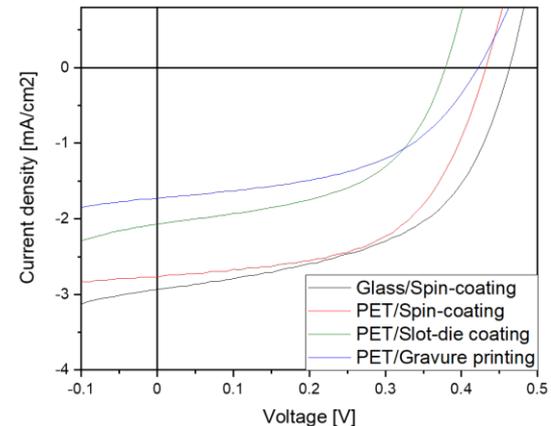
- World record on glass / controlled atmosphere: ~2.5%
 - Tampere University ~1.0%
 - VTT: 0.77% / glass and 0.76% / flex
- No article on flexible $\text{Cu}_2\text{AgBiI}_6$ (CABI) devices



Results



Champion cells	PCE [%]	Voc [V]	Jsc [mA/cm ²]	FF [%]
Glass / Spin	0.77	0.46	3.06	54.30
Flex / Spin	0.76	0.46	2.86	57.66
Flex / Slot-die coating	0.41	0.38	2.07	51.81
Flex / Gravure printing	0.36	0.42	1.73	49.46



Results

- SEM analysis reveals distinct morphological features influenced by deposition methods.
- Differences observed in uniformity, surface coverage, and roughness, and crystal orientation.
- Device fabrication on flexible substrate proved to yield similar performance as to the device fabricated on glass.

Multi-sensory environmental sensing for enhanced sensitivity and selectivity

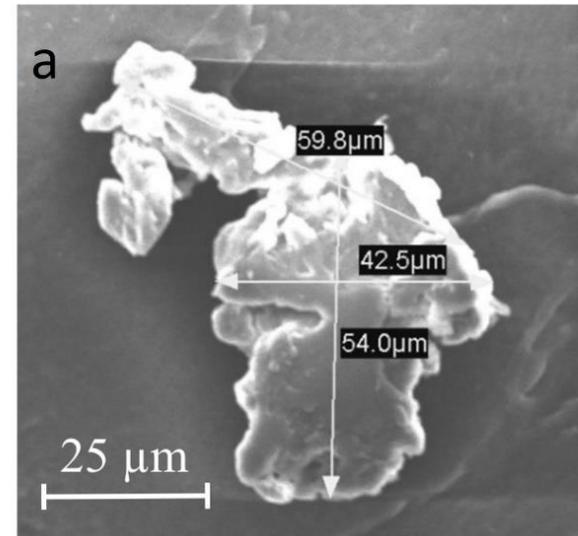
Juha Toivonen, Tampere University

Sample preparation

We prepare MPs of different types using milling of commercial plastic sheets [1].

- Scanning electron microscopic picture of a polypropylene microplastic fabricated by milling.
- Photograph of the ten grinded microplastic samples.
- Photograph of the elongated and circular cuvettes.
- Arrangement of the cuvettes and sample holders on the measurement table.

[1] B. Hrovat, E. Uurasjärvi, A. Koistinen, K. Peiponen, M. Roussey, M. Viitala, "Preparation of Synthetic Micro- and Nanoplastics for Method Validation Studies," *Science of The Total Environment* **925**, 17182 (2024)

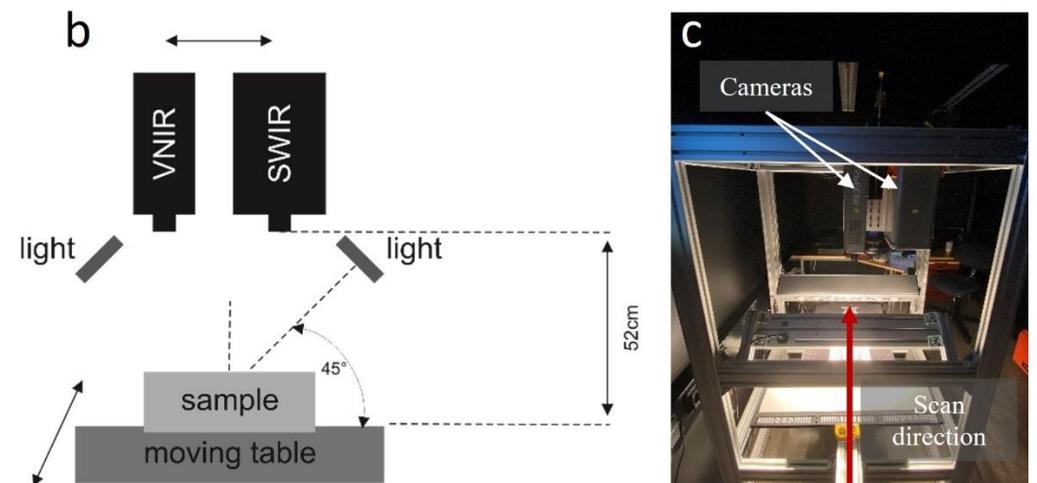
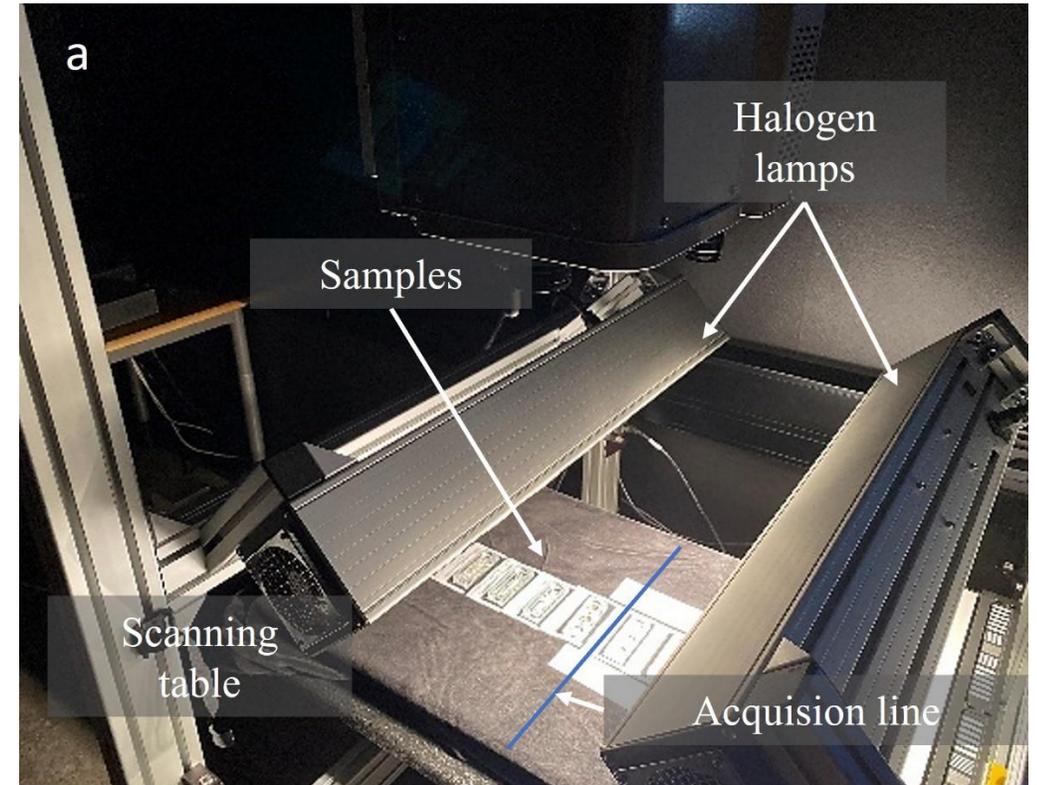
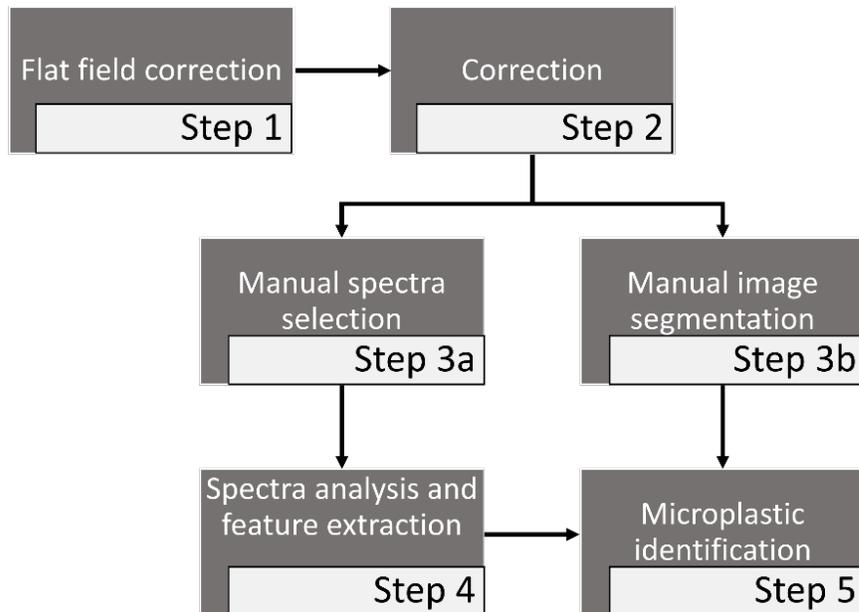


Hyperspectral imaging

Microplastics are mixed with tap water.

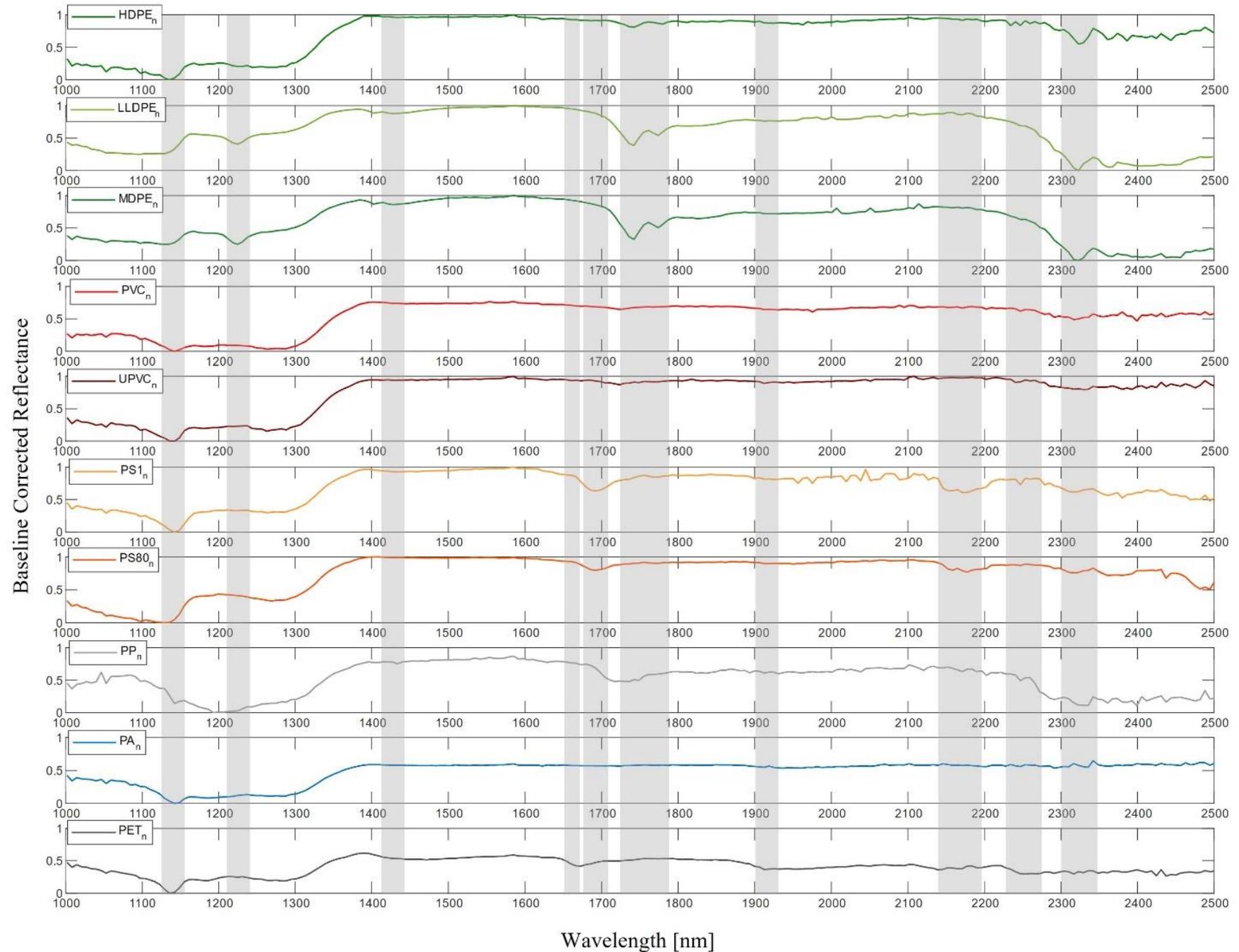
a) Schematics of the setup.

b) and c) Photographs of the experimental setup.



Spectra

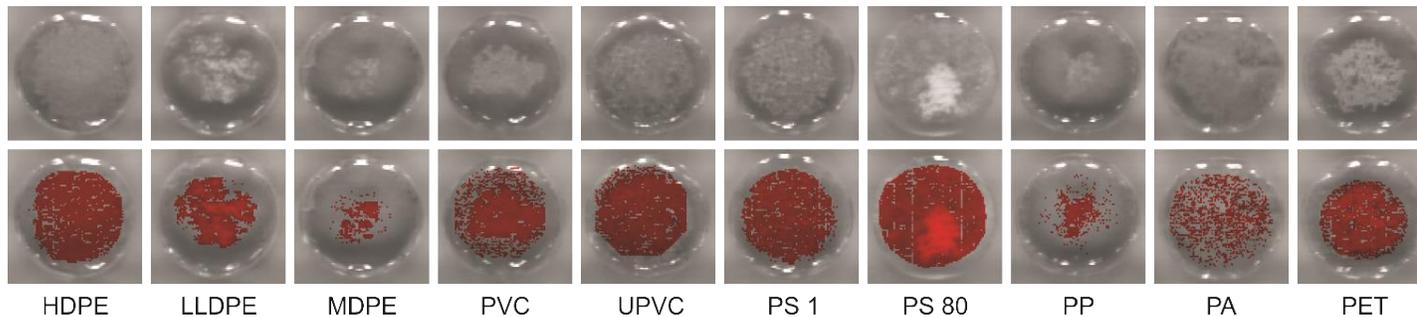
- Subtraction of water spectrum
- Correction with 1550 nm
- Gray stripes mark the main spectral features.



Analysis and identification

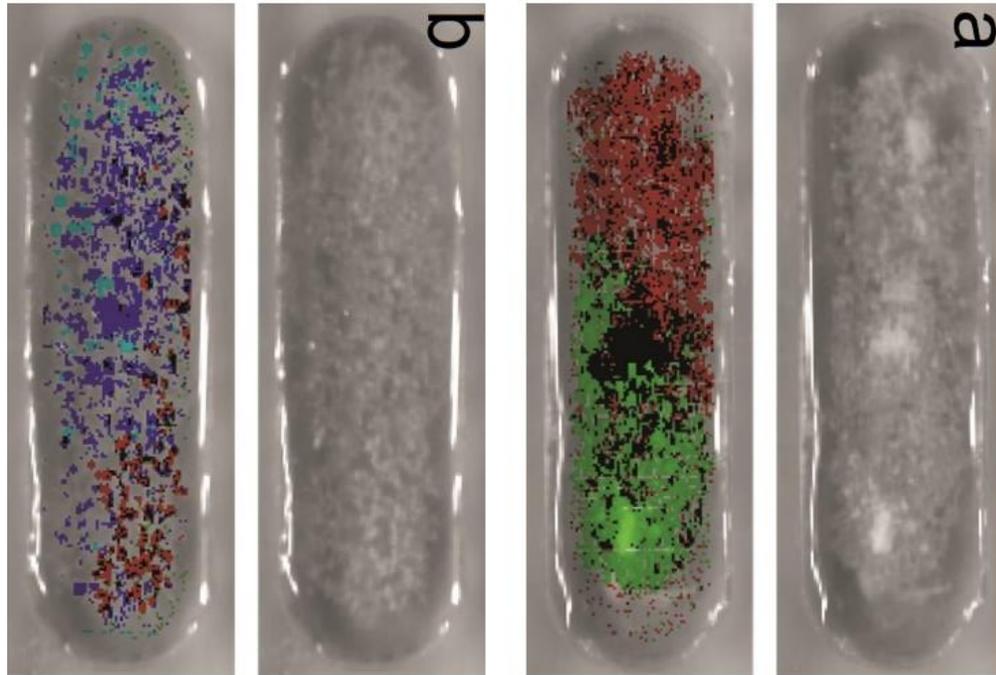
- Using derivative of the spectra to build a decision table

MP type	Spectral Features (nm)													
	1130	1661	1680	1698	1717	1736	1768	1906	2146	2171	2241	2266	2317	2355
HDPE						1	1						1	1
LLDPE						1	1						1	1
MDPE						1	1						1	1
PVC					1	1								
UPVC					1	1								
PS1			1						1	1				
PS80			1						1	1				
PP				1								1		
PA	1					1				1				
PET		1						1			1			



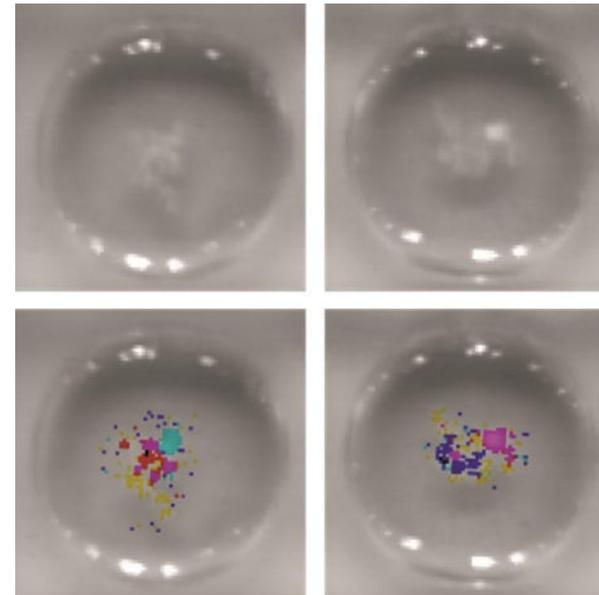
- Individual MP identification test
- Overlaid with the microplastics identification mask

Identification of microplastic mixtures



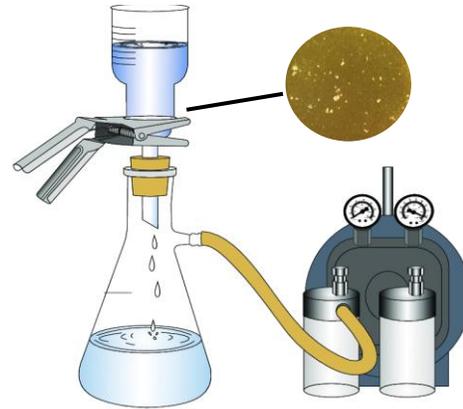
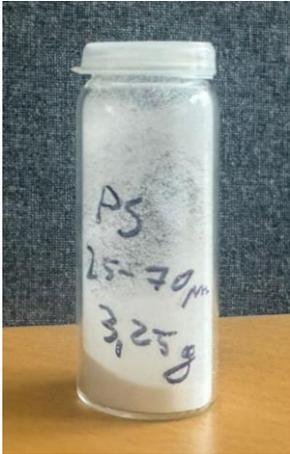
- PP
- UPVC/PVC
- PA
- PET
- unclassified

- PS 1/PS 80
- HDPE/LLDPE/MDPE
- unclassified

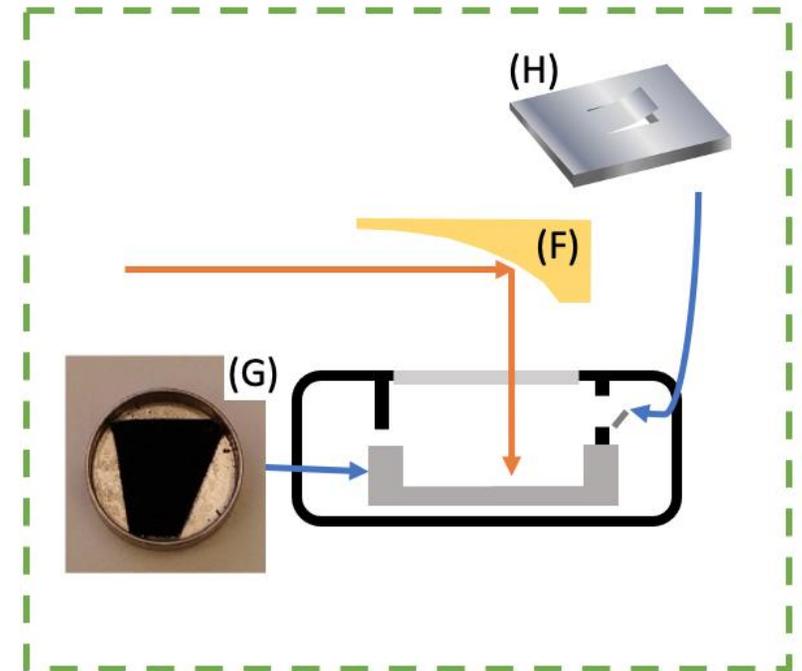
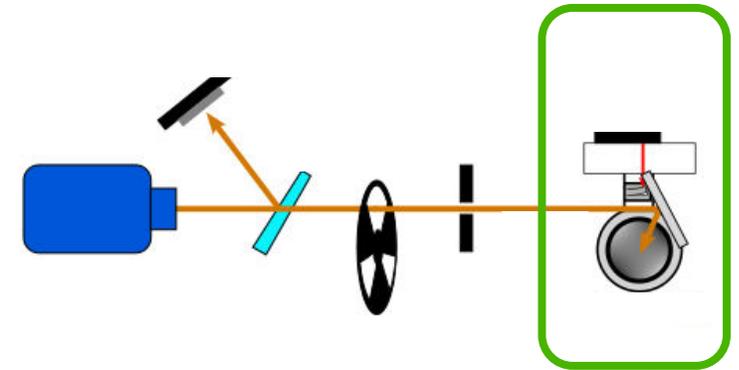


- PP
- UPVC/PVC
- PA
- PET
- HDPE/MDPE/LLDPE
- PS 1/PS 80
- unclassified

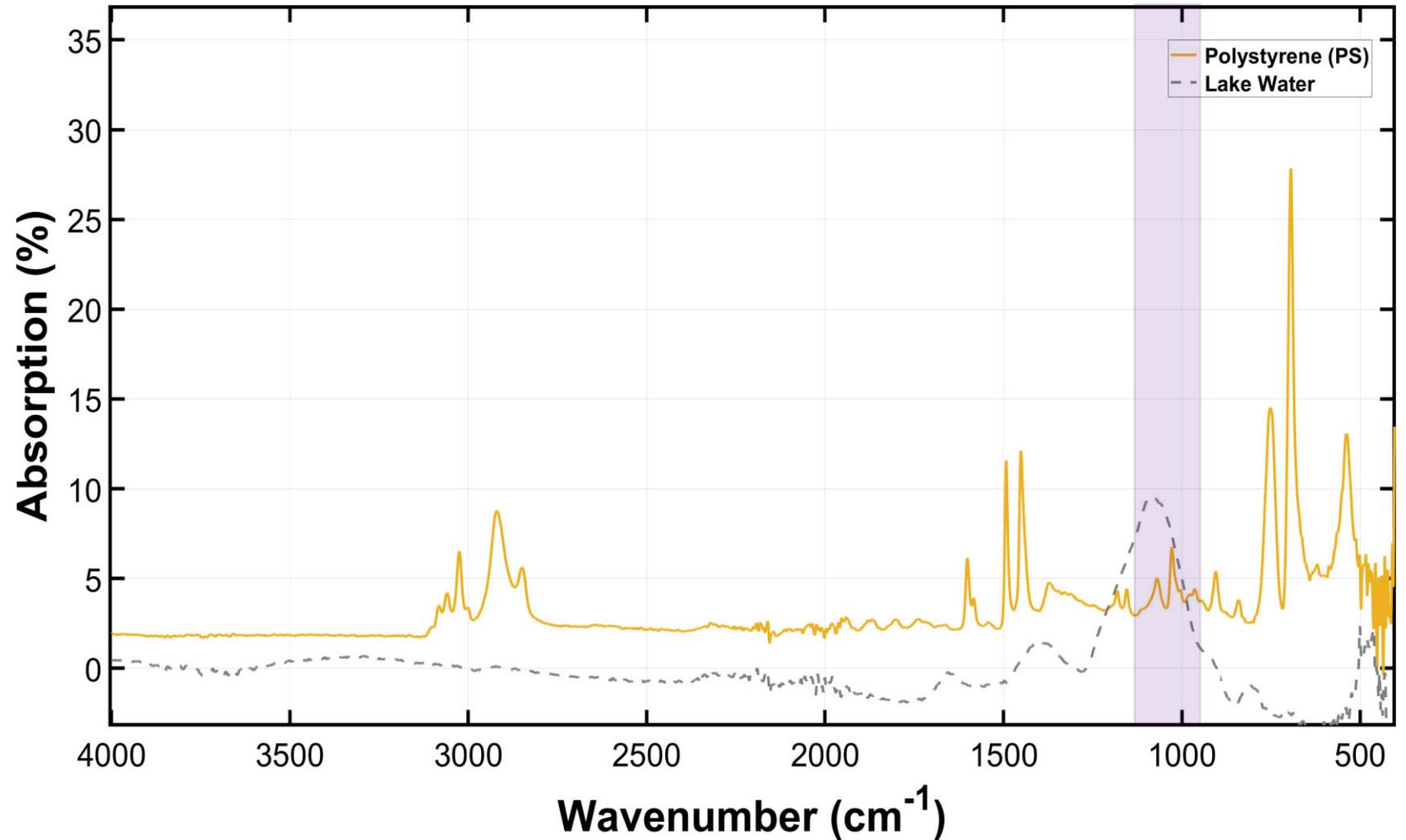
FTIR and photoacoustic spectroscopy



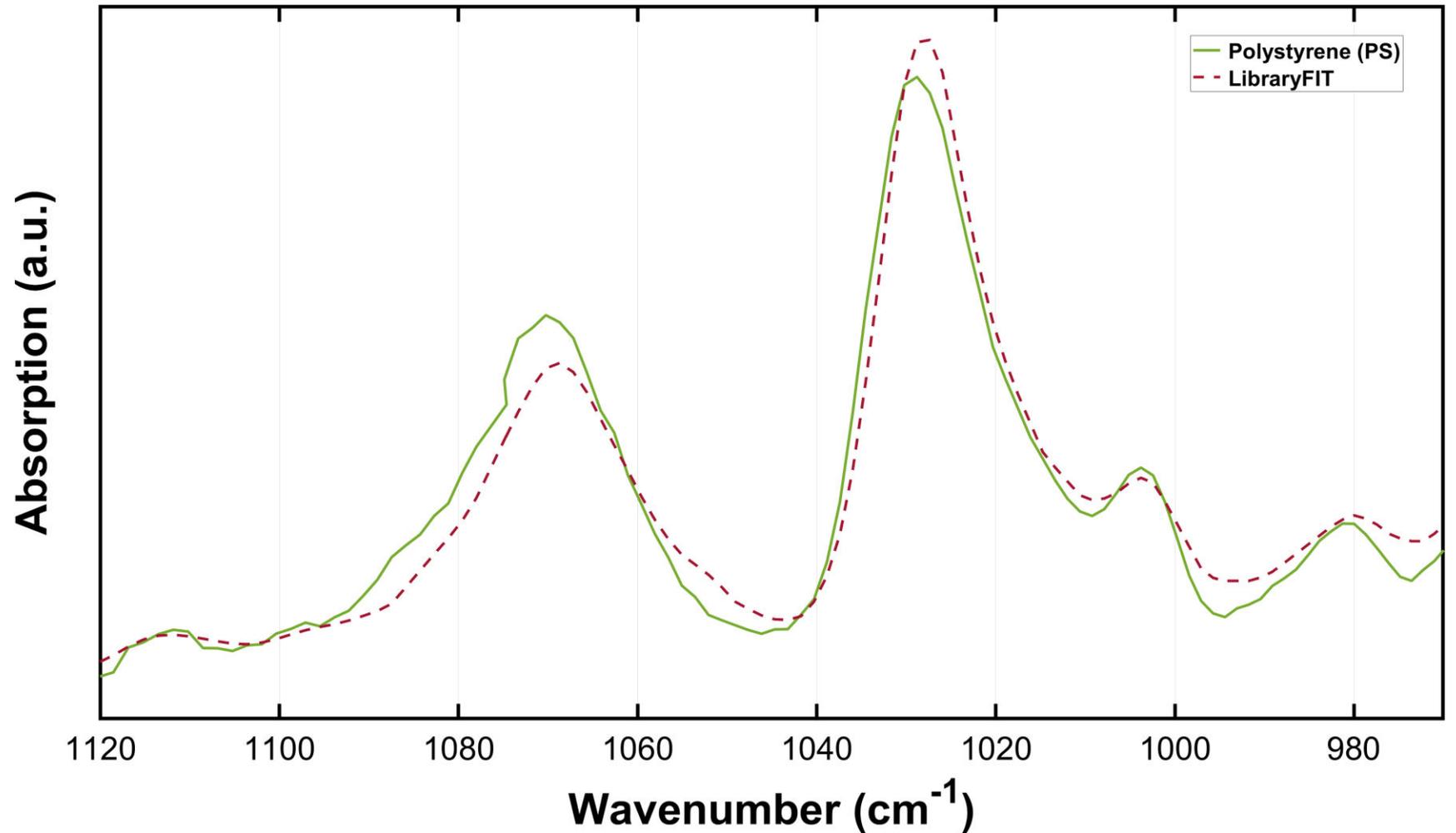
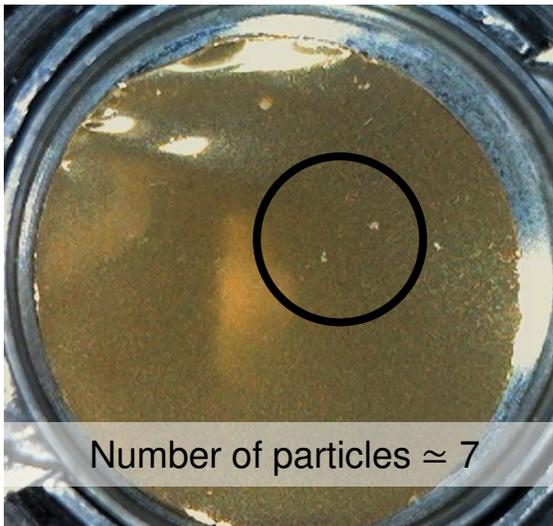
9 mm



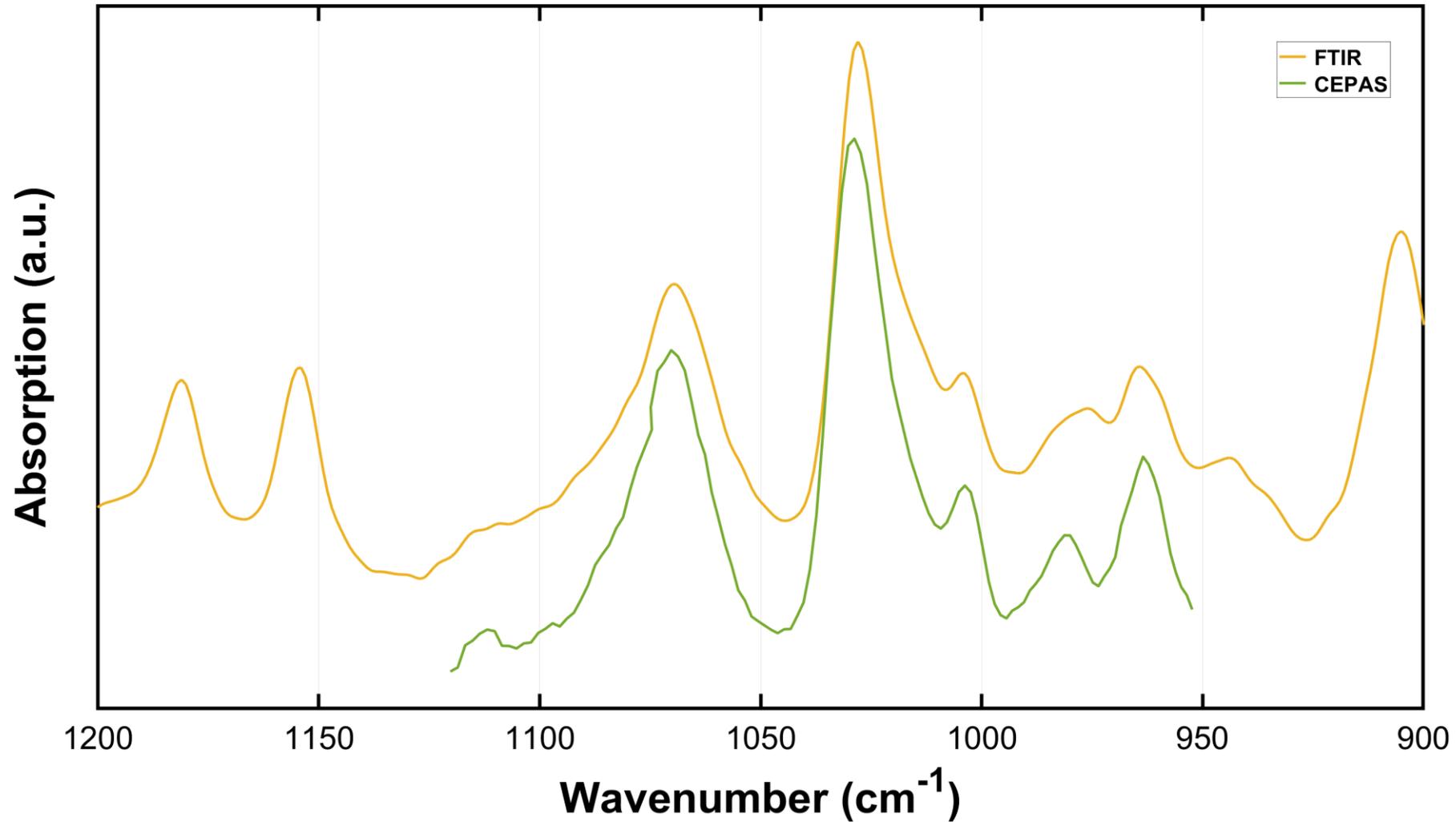
FTIR using large number of particles



Photoacoustic sensing with less particles

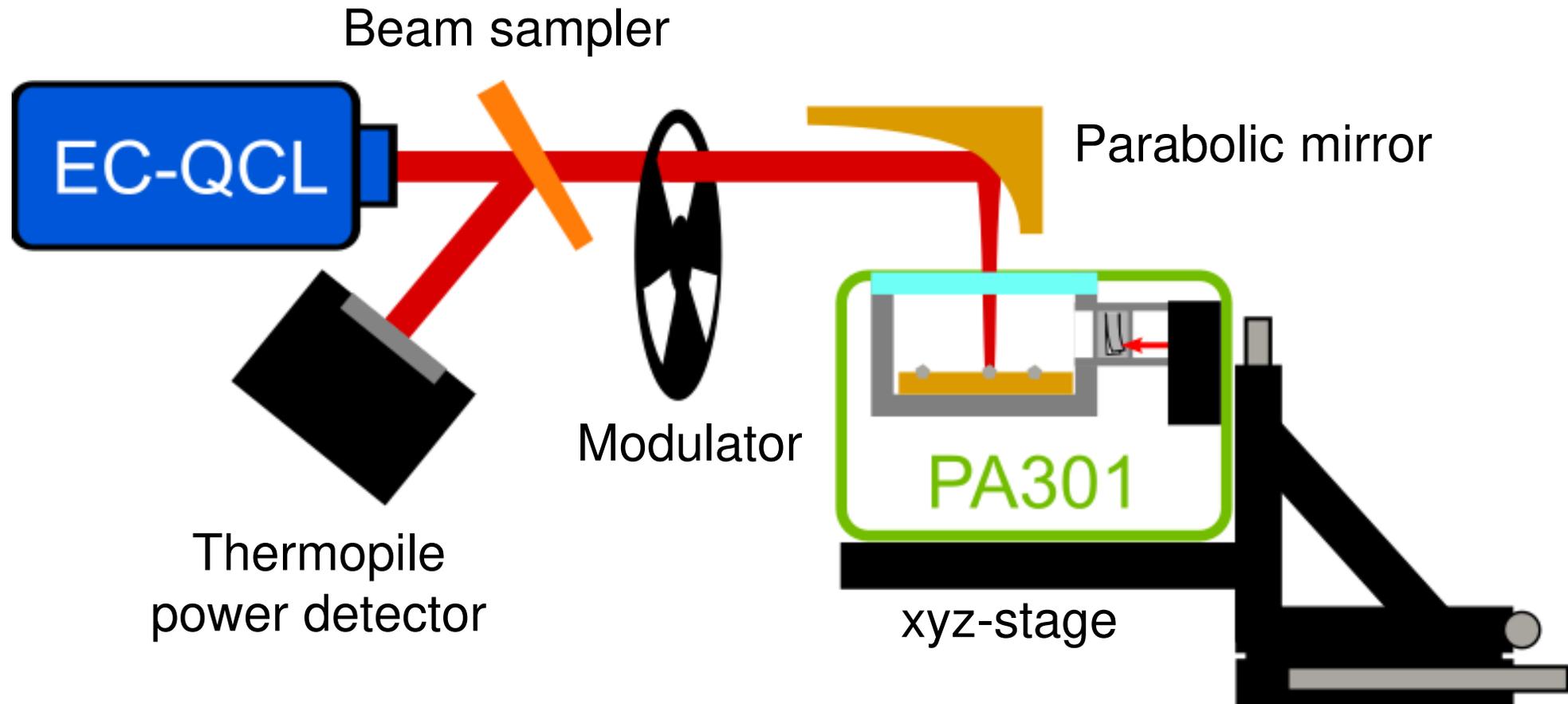


Comparison of FTIR and photoacoustic

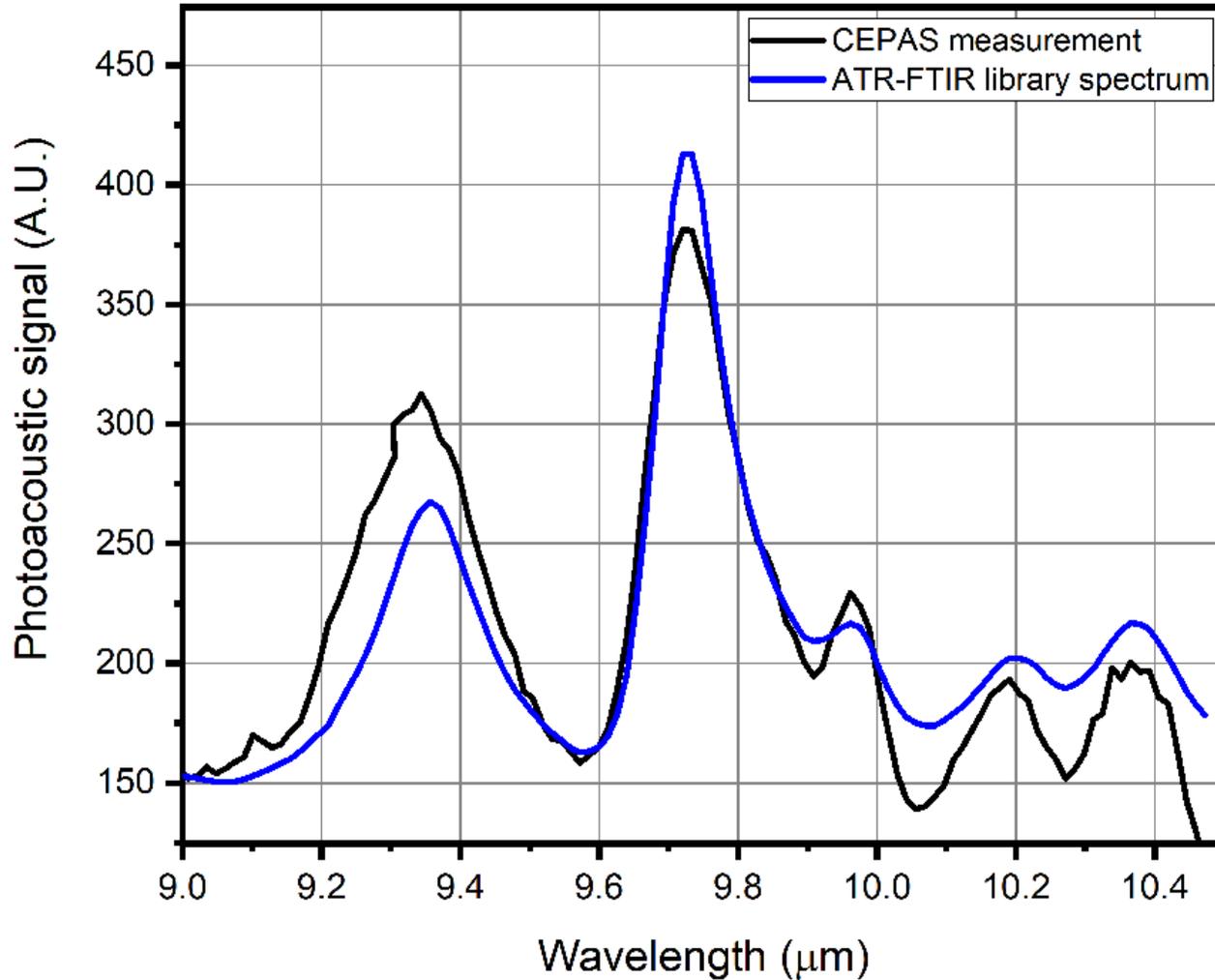


Setup

- Wavelength range 8.5-10.5 μm
- Beam size $\sim 300 \mu\text{m}$ at sample



Example spectrum



- Single particle polystyrene spectrum
- Particle size: 25-70 μm

Conclusion

- Own microplastic particle production for testing
- Hyperspectral imaging
- Fourier-transform spectroscopy
- Photoacoustic spectroscopy with tunable laser
- Sensitivity down to single particle level

Structured Quantum Photonics with Geometric Phases and Integrated Circuits

PREIN Annual Event, OPD 2024



28th May 2024, Helsinki

George Thomas, Vladimir Kornienko

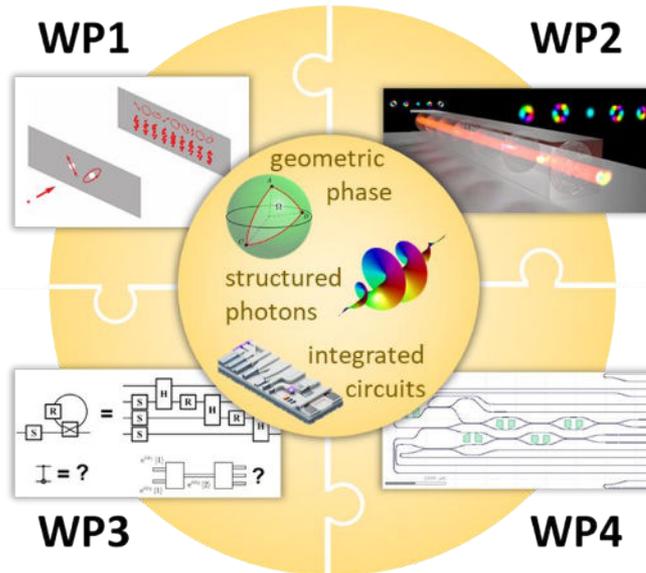


Introduction

- Project aims the combination of Quantum Optics, Structured Light, and Integrated Optics.
- Fundamental theoretical aspects of the geometric phase in quantum optics.
- Experimental implementations with structured free-space optics and photonic integrated circuits.

Geometrical phase and its relation with wave-particle duality: UEF

Geometric phase related to multiphotons, photonic quantum computing: AALTO



Structured light: TAU

Photonic integrated circuits: VTT

Introduction

Phases in Quantum dynamics

Geometric phase (Pancharatnam–Berry phase): Phase accumulated during the evolution of the system due to the geometrical properties of Hamiltonian's parameter space and usually observed in cyclic evolution [1,2].

Dynamical phase: Phase accumulated due to the energy of the quantum system during the evolution.

Structured photons: Higher dimensional systems of light with arbitrary coherent superposition of polarizations and spatial modes [3,4].

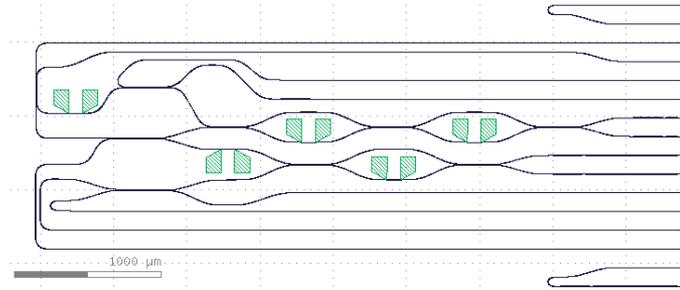
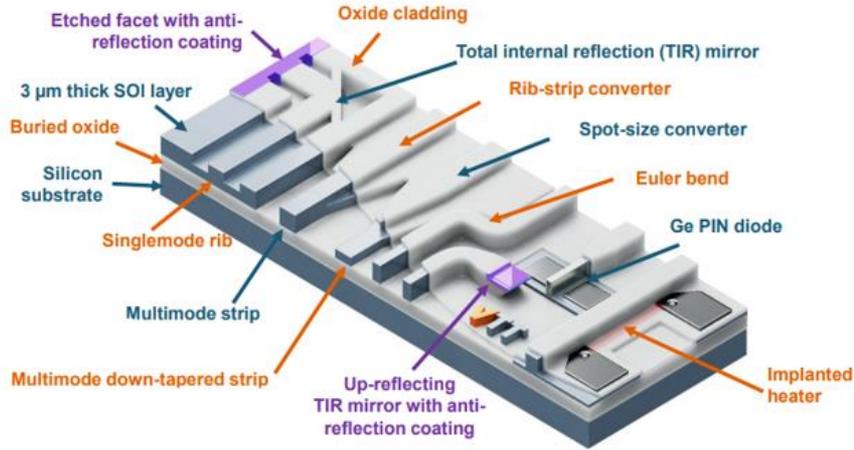
[1] S. Pancharatnam Proc. Indian Acad. Sci. A. **44** 247 (1956).

[2] M. V Berry, Proceedings of the Royal Society A. **392** 45 (1954).

[3] E. Nagali et al, Phys. Rev. A **81**, 052317 (2010).

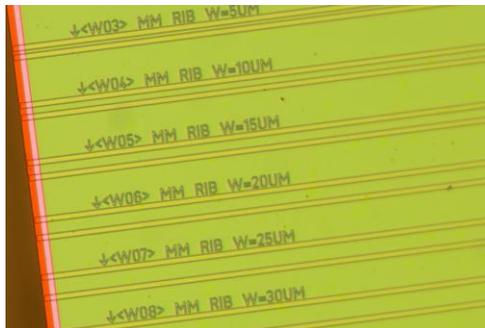
[4] A. St et al, Optica **4** 1006 (2017).

Photonic integrated circuits



Photonic CNOT gate on thick SOI platform (Aalto/VTT)

VTT's 3 μm thick SOI platform is a useful candidate for the quantum technologies [Ref: Advanced Photonics Nexus 2, 024002 (2023).]



Chip with multimode waveguides are fabricated in thick SOI platform for coupling structured light modes to waveguide modes (TAU/VTT)

High-dimensional interface for structured light

Idea:

using multiplane light conversion (MPLC) technique to implement high-dimensional interface between free-space and on-chip multi-mode light fields

free space modes:

- Laguerre Gauss modes $LG_{p,l}$

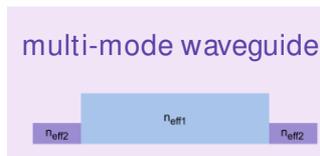
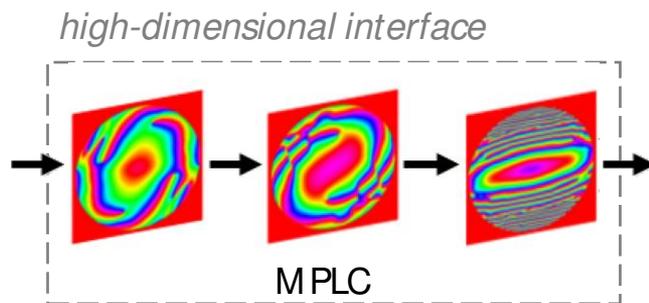


$LG_{0,0}$ $LG_{0,1}$ $LG_{0,2}$

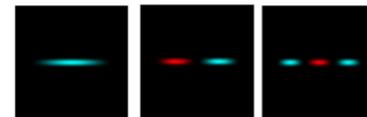
- Hermite Gauss modes $HG_{n,m}$



$HG_{0,1}$ $HG_{0,1}$ $HG_{1,1}$

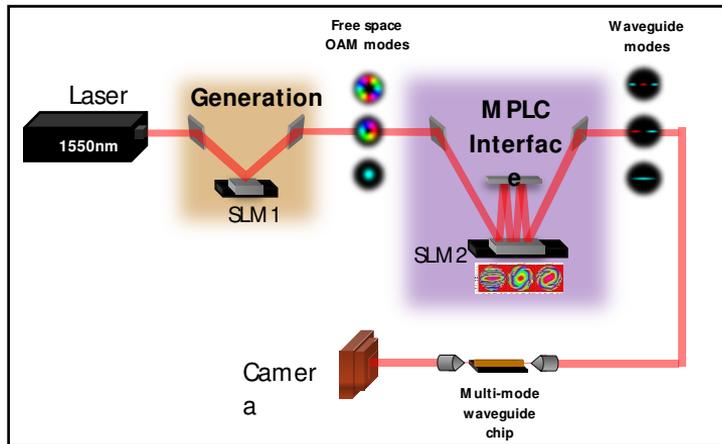


waveguide modes:



High-dimensional interface for structured light

Experimental implementation

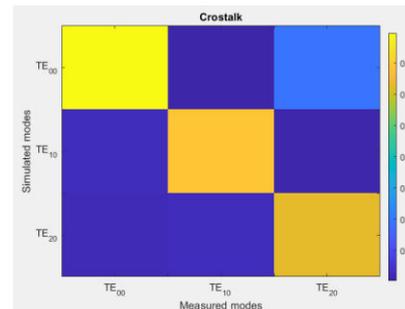


Simplified drawing of the experimental set-up

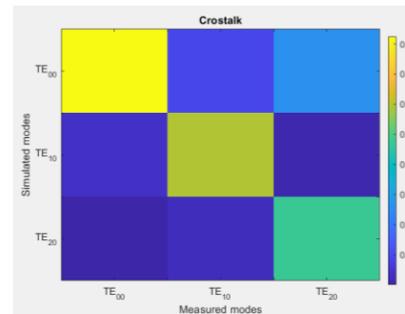
Measured cross talks

Preliminary results

Laguerre-Gauss



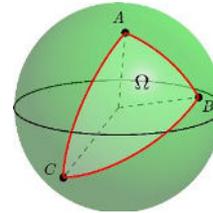
Hermite-Gauss



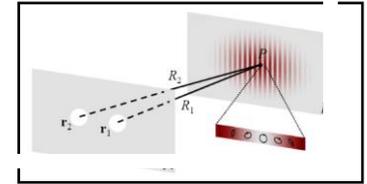


Geometric phase and wave–particle duality

- Pancharatnam–Berry phase [1]: $|\Phi_G| = \Omega/2$
 - geometric phase that vectorial light gains as its polarization state undergoes a cyclic evolution
 - occurs even if the dynamical phase is absent
 - fundamental (wave) property of the photon [2]



Observed in two-slit interference with classical light fields [3,4]



- Photon in double-slit setup [5]: $|\Phi'_G| + \Upsilon \leq 1$
 - $0 \leq |\Phi'_G| \leq 1$ and $0 \leq \Upsilon \leq 1$



$$\Phi'_G = \Phi_G/\pi$$

$$\Upsilon = D_0/D_S$$

wave aspect particle aspect

- In cyclic polarization evolution: $|\Phi'_G| + \Upsilon = 1$



Strong complementarity!

[1] E. Cohen et al., *Nat. Rev. Phys.* **1**, 437 (2019).
 [2] P. G. Kwiat & R. Y. Chiao, *Phys. Rev. Lett.* **66**, 588 (1991).
 [3] A. Hännönen, H. Partanen, A. Leinonen, J. Heikkinen, T. K. Hakala, A. T. Friberg & T. Setälä, *Optica* **7**, 1435 (2020).

[4] A. Leinonen, A. Hännönen, H. Partanen, J. Heikkinen, T. Setälä, A. T. Friberg & T. K. Hakala, *Commun. Phys.* **6**, 132 (2023).
 [5] E. Pillinen, A. Halder, A. T. Friberg, T. Setälä & A. Norrman, *arXiv:2310.20273* (2023).



Geometric phase with NOON states

- Four-mode NOON state at the slit plane \mathcal{A} :

$$|\psi\rangle = c_{1x}|N, 0, 0, 0\rangle + c_{1y}|0, N, 0, 0\rangle \\ + c_{2x}|0, 0, N, 0\rangle + c_{2y}|0, 0, 0, N\rangle$$

- Four Stokes operators ($j = 0, 1, 2, 3$):

$$\hat{S}_j^{(N)}(\mathbf{r}_1, \mathbf{r}_2) = |C|^{2N} [\hat{a}_{1x}^{\dagger N} \hat{a}_{1y}^{\dagger N}] \boldsymbol{\sigma}_j [\hat{a}_{2x}^N \hat{a}_{2y}^N]^T$$

- Polarization modulation at the screen \mathcal{B} :

$$S_j^{(N)}(\mathbf{r}) = \frac{|K|^{2N}}{r^{2N}} \left[S_j^{(N)}(\mathbf{r}_1) + S_j^{(N)}(\mathbf{r}_2) + 2 \left| S_j^{(N)}(\mathbf{r}_1, \mathbf{r}_2) \right| \cos \left(Nk\Delta r + \theta_j(\mathbf{r}_1, \mathbf{r}_2) \right) \right], \Delta r = r_2 - r_1$$

- Poincaré-type sphere for the NOON state:

$$\left[S_0^{(N)}(\mathbf{r}) \right]^2 = \left[S_1^{(N)}(\mathbf{r}) \right]^2 + \left[S_2^{(N)}(\mathbf{r}) \right]^2 + \left[S_3^{(N)}(\mathbf{r}) \right]^2$$

- Geometric phase in one cycle: $\Phi_G^{(N)} = \pm \pi(1 - \Upsilon^{(N)})$

$$\text{WPI ratio: } \Upsilon^{(N)} = D_0^{(N)} / D_S^{(N)}$$

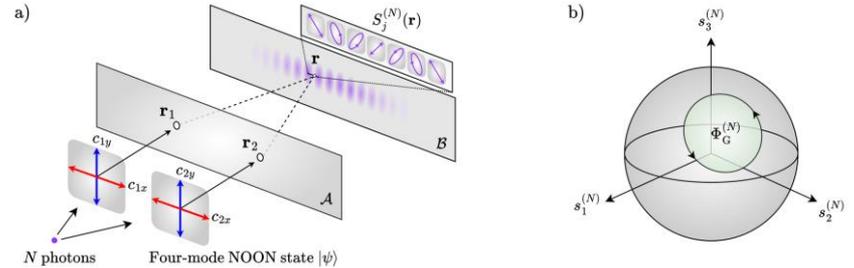
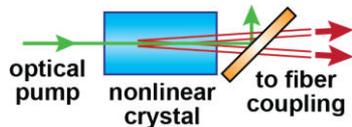


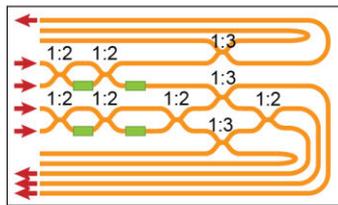
Fig 1. NOON-state polarization modulation a) in double-slit interference and b) on a Poincaré-type sphere.

N times faster polarization evolution and geometric-phase accumulation!

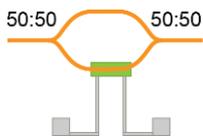
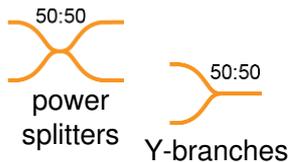
Photonic integrated circuits – control and photon source optimization



Photon source schematic



Non-deterministic CNOT gate

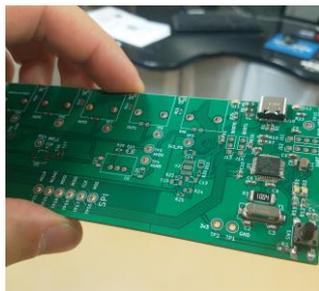


Mach-Zehnder interferometers

- Design a source of heralded single photons and biphotons @ infrared range ($> 1.3 \mu\text{m}$).
- Test the performance of photonic integrated circuits (PICs) at the single-photon level.
- Reconstruct the transfer matrix \mathbf{M} matrix of a PIC device.

A lossless linear optical multiport device can be characterized by the transfer matrix \mathbf{M} :

$$\begin{pmatrix} \hat{a}_1^{\text{out} \dagger} \\ \hat{a}_2^{\text{out} \dagger} \\ \dots \end{pmatrix} = \mathbf{M} \begin{pmatrix} \hat{a}_1^{\text{in} \dagger} \\ \hat{a}_2^{\text{in} \dagger} \\ \dots \end{pmatrix}$$



Controller for thermo-optical phase shifters (PCB stage):
ARM microcontroller + voltage output DAQs, 7 channels. kHz rate.

An optical multiport with an arbitrary number of inputs and outputs can be characterized with a source of biphoton pairs via the Hong-Ou-Mandel (HOM) interference.

HOM interference visibility:

$$V_{ijkl} = (C_{ij}^{kl} - Q_{ij}^{kl}) / C_{ij}^{kl}$$

(\approx boson sampling, reversed.)

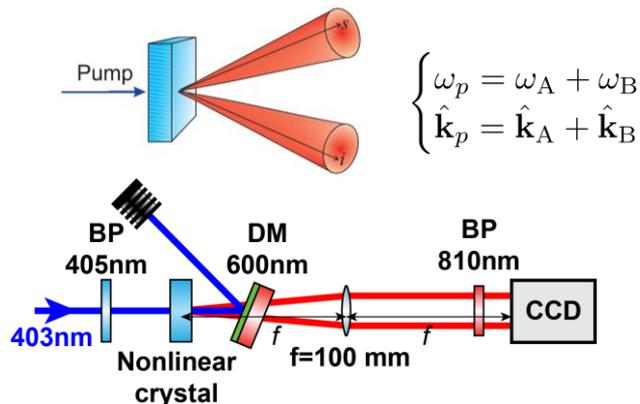
Indistinguishable photons:

$$Q_{ij}^{kl} = \frac{1}{1 + \delta_{ij}} |M_{ik}M_{jl} + M_{il}M_{jk}|^2$$

Distinguishable photons:

$$C_{ij}^{kl} = |M_{ik}M_{jl}|^2 + |M_{il}M_{jk}|^2$$

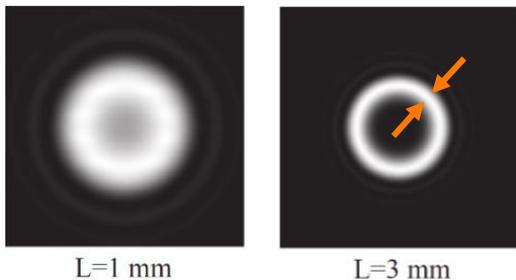
Photonic integrated circuits – control and photon source optimization



- ❑ Lack of accessible infrared detectors: visible light characterization + dispersion-based computations
- ❑ Spontaneous parametric down-conversion (SPDC) as a probing tool: zero-field vacuum fluctuations span the whole frequency range and have uniform brightness.
- ❑ Use the biphoton amplitude to compute the correlation moments.

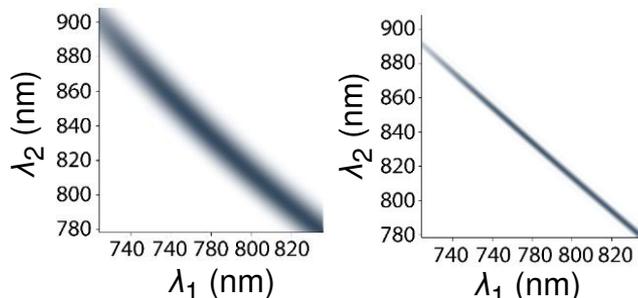
A biphoton field amplitude $\Psi(\mathbf{k}_1, \mathbf{k}_2)$ can be computed using the formalism of macroscopic nonlinear optics.

Unconditional photon detection probability (single counts):



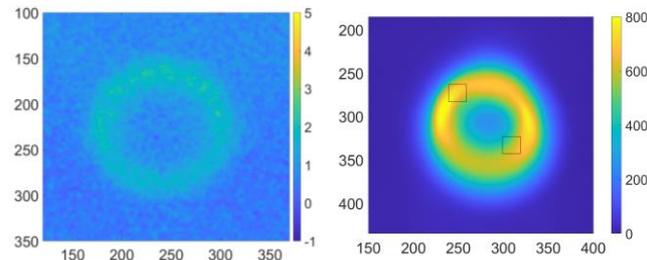
$$\frac{dw^{uncond}}{dk_{1\perp x}} = \int dk_{2\perp x} |\Psi(k_{1\perp x}, k_{2\perp x})|^2$$

Conditional photon detection probability (coincidences):



$$\frac{dw^{cond}}{dx_1} = \frac{|\Psi(k_{1\perp x}, k_{2\perp x})|^2}{\int dk_{1\perp x} |\Psi(k_{1\perp x}, k_{2\perp x})|^2} \Big|_{k_{2\perp x}}$$

Measurements at $\lambda_p = 403$ nm:



type-I BiBO 0.25 mm, type-I BBO 10.0 mm
 Optical pump: 403 nm, continuous wave, 10 mW
 CCD camera: no gain, 0.1-1s exposure times

Thank You!!



Main contacts:

Prof. Ilkka Tittonen (AALTO)

Dr. Robert Fickler (TAU)

Dr. Andreas Norrman (UEF)

Dr. George Thomas (VTT)





Integrated pulsed laser driving industrial scaling of quantum technology – IntegrateQT –

Mircea Guina, Prof.

Optoelectronics Research Centre, Photonics / Physics Unit
Faculty of Engineering and Natural Sciences,
Tampere University

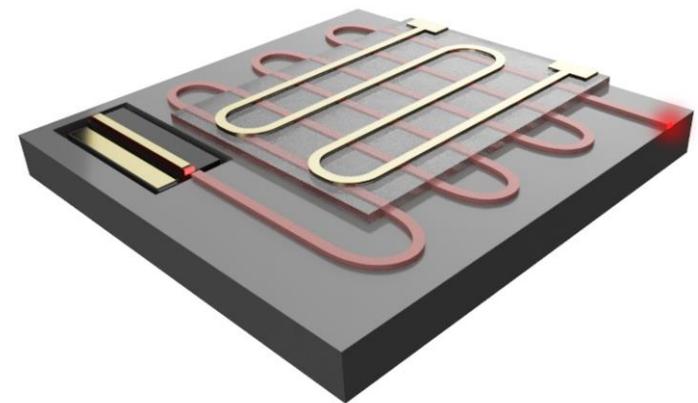
www.research.tuni.fi/orc

www.tuni.fi/photonics

www.prein.fi

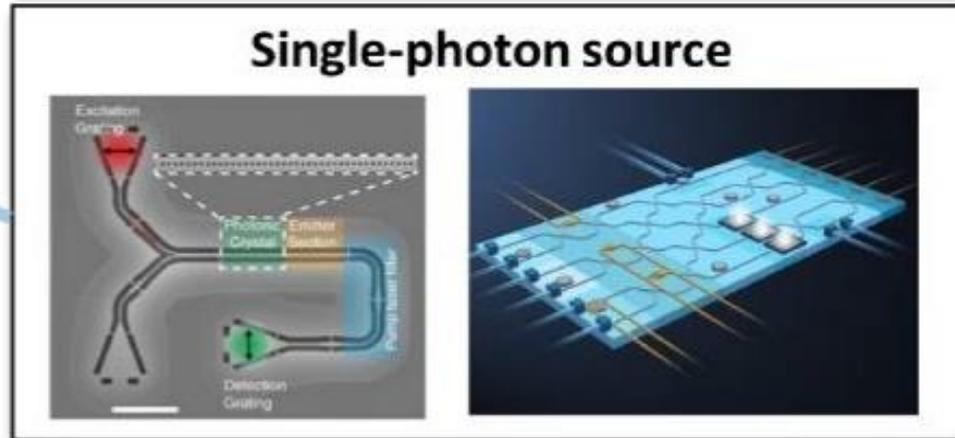
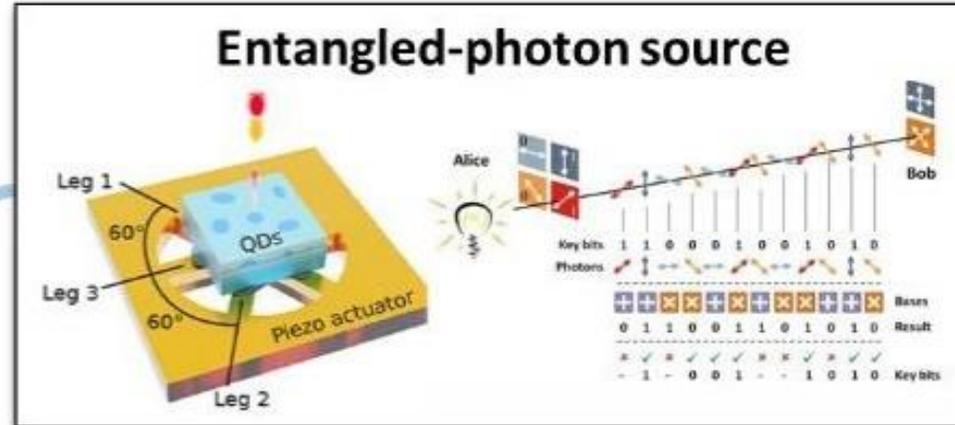
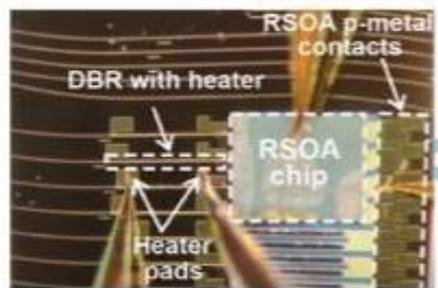
<https://www.linkedin.com/in/mircea-guina/>

mircea.guina@tuni.fi

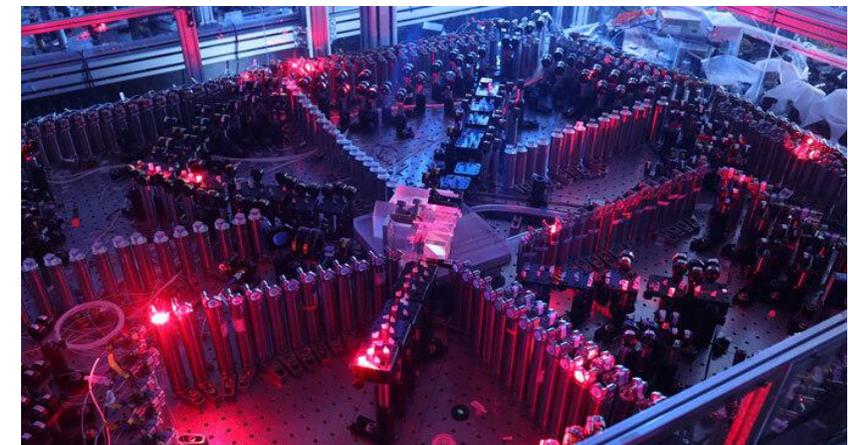
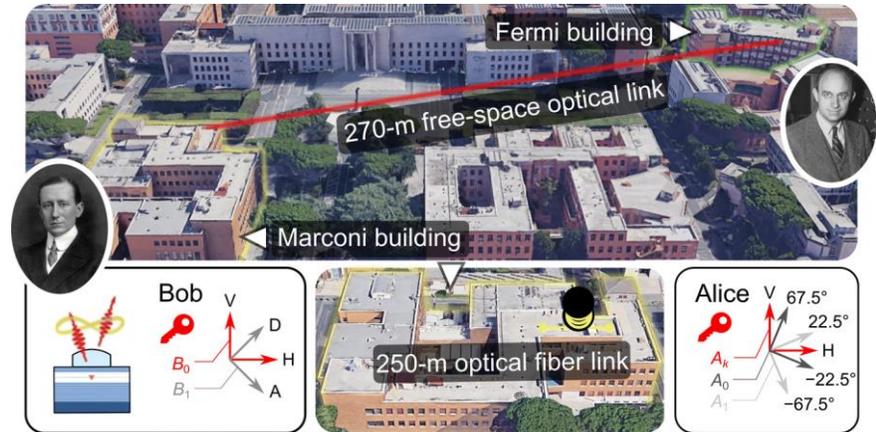


Project in a nutshell

PIC pulsed triggers



HAN-SEN ZHONG et al. Science 370, 1460 (2020)

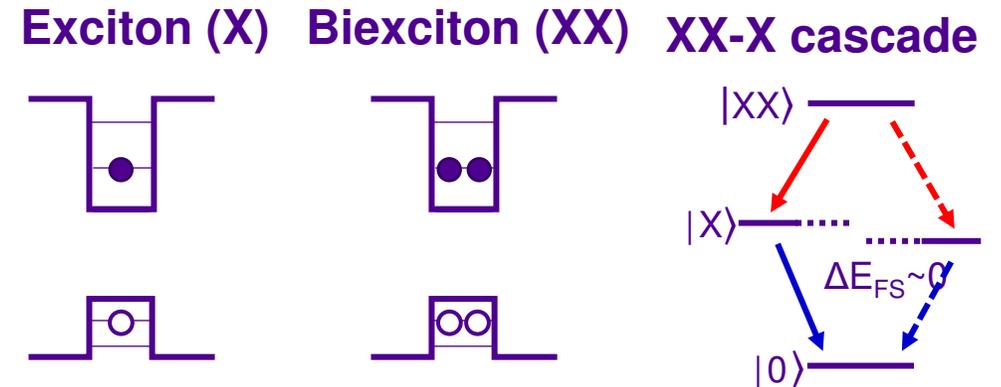
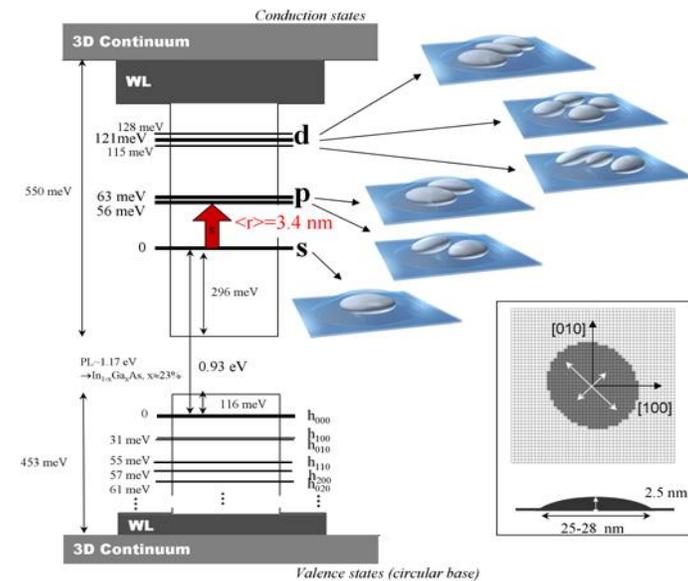


F. B. Basset et al. Sci. Adv. 7, 6379 (2021)

General goal: development of PIC-based mode-locked lasers and demonstrate their applicability for single and entangle-photon generation with QDs @780 nm, @940nm, and @1.5 μm wavelengths.

Benefits of semiconductor Quantum Dots

- **Artificial atoms** with tailorable emission wavelength
- **Compatibility** for integration with semiconductor electronic, optoelectronic and integrated photonic platforms
 - Photonic integration
 - Semiconductor DBR mirrors and vertical cavities
 - P-I-N junctions for applying gate voltage
- **Single-photon emission** from exciton recombination
 - Fast spontaneous lifetime
- **Polarization entangled-photon** emission from biexciton-exciton cascade (if small FSS)
- **An ideal single-photon source:**
 - Triggered photons on-demand
 - High repetition rate
 - All photons are identical – indistinguishability
 - 100% fidelity of entanglement



QDs vs. Spontaneous Parametric Down-Conversion

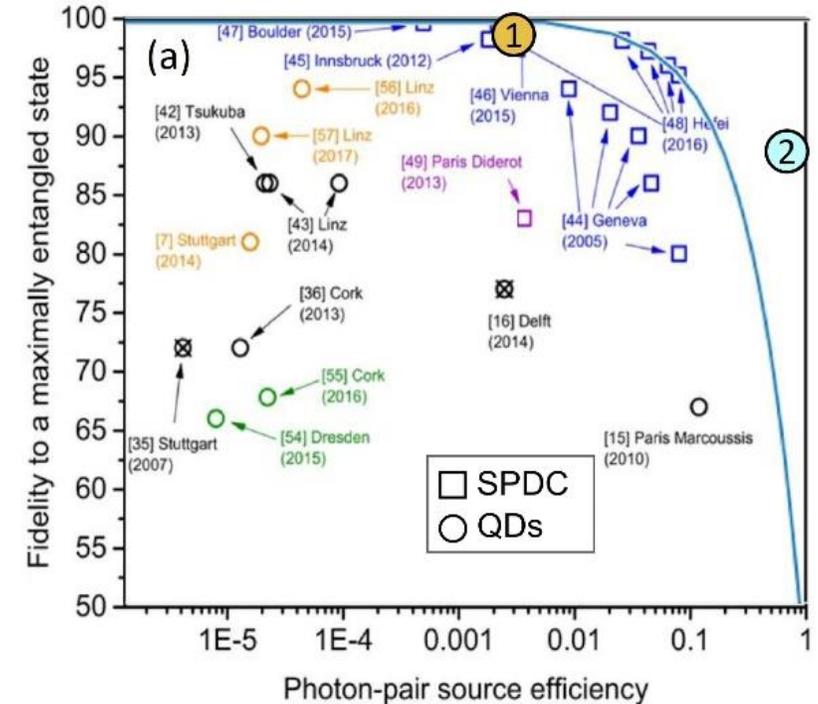
QDs are single-atom-like deterministic emitters

→ Possibility to achieve **high photon rate** and **high fidelity of entanglement** simultaneously

SPDC is a probabilistic process

→ Increase of photon rate increases the number of multiphoton events

→ Degradation of entanglement and single photon quality

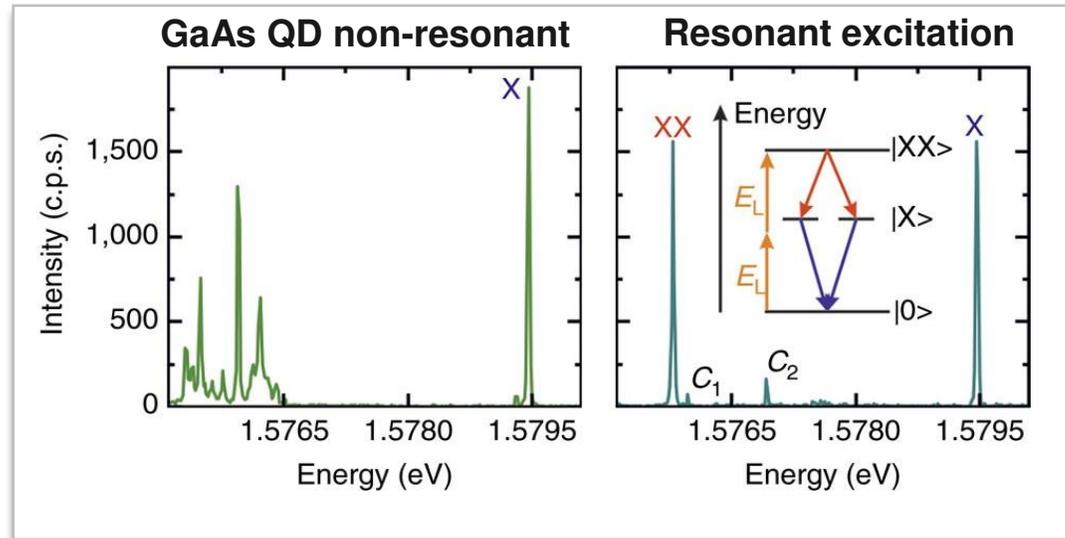


[1] D. Huber et al. (A. Rastelli) Phys. Rev. Lett. **121**, 033902 (2018)

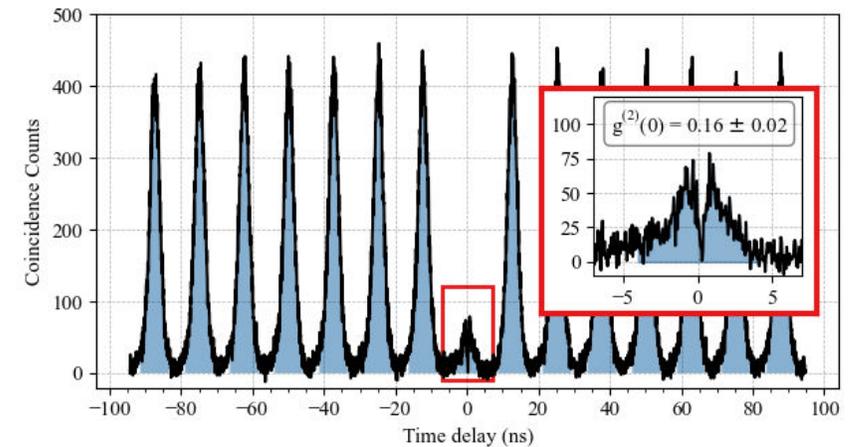
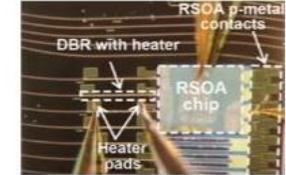
[2] Jin Liu et al. (A. Rastelli) Nature Nanotechnology **14**, 586 (2019)

The scalability issue

- Use of complex and expensive excitation lasers (TiSa, OPO)
 - Tuned in resonance with the QD emission to avoid charge accumulation outside QDs



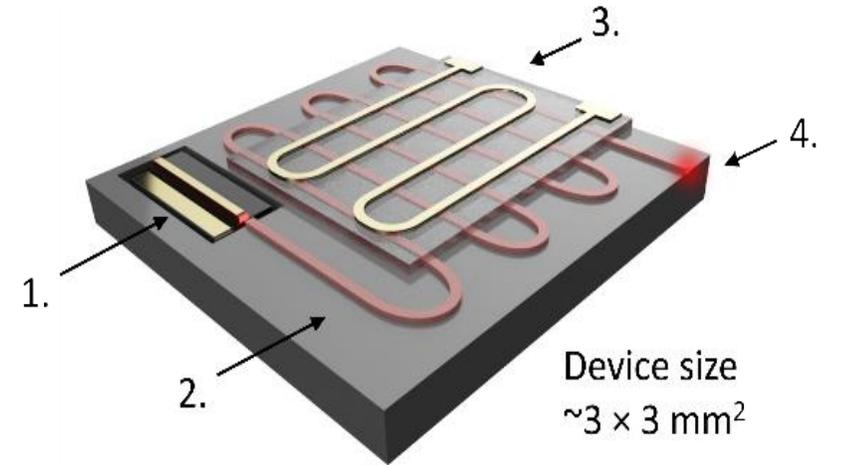
D. Huber et al. Nature Communications 8, 15506 (2017).



- Need: a fully-integrated chip-based excitation source for resonant excitation

Specific goals

- **Wavelength range:**
 - 780+/-1nm for GaAs/AlGaAs QDs
 - 940+/-1nm for InGaAs/GaAs QDs
 - 1500+/-2nm GaSb/AlGaSb QDs
- **Average power:** a few mW
- **Pulse duration:** <30 ps is sufficient for the PoC; SoA <10ps (sets the upper limit for the fidelity entanglement)
- Spectral width of < 0.5 nm
- **Repetition rate:** 0.5 – 2 GHz. Limited by the spontaneous lifetime of the QD material (~200ps for GaAs QDs and ~700ps for InGaAs QDs). Use an optical cavity to enhance the spontaneous rate of the QD (x10).



(1) Optoelectronic gain chip with saturable absorber section; (2) A SiN PIC chip forming an extended waveguide cavity; (3) a heating element for wavelength tuning; and (4) an output port for fibre coupling to QIPC.

- **Main challenge: coupling losses and spurious reflections at Gain Chip / PIC interface.**

Links to PREIN WPs (WP3 & WP4)

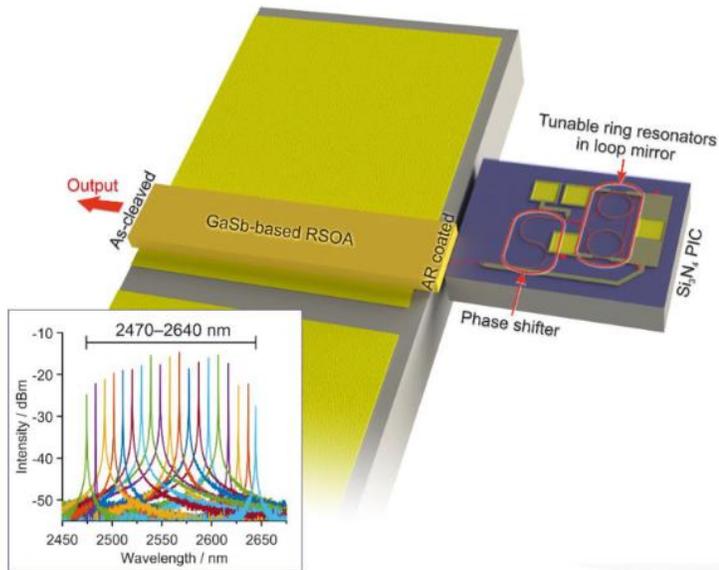
LASER & PHOTONICS REVIEWS

Research Article [Open Access](#)

Widely Tunable (2.47–2.64 μm) Hybrid Laser Based on GaSb/GalnAsSb Quantum-Wells and a Low-Loss Si₃N₄ Photonic Integrated Circuit

Samu-Pekka Ojanen , Jukka Viheriälä, Nouman Zia, Eero Koivusalo, Joonas Hillska, Heidi Tuorila, Mircea Guina

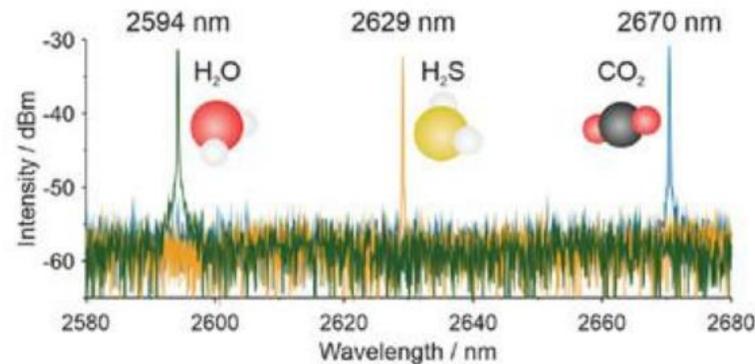
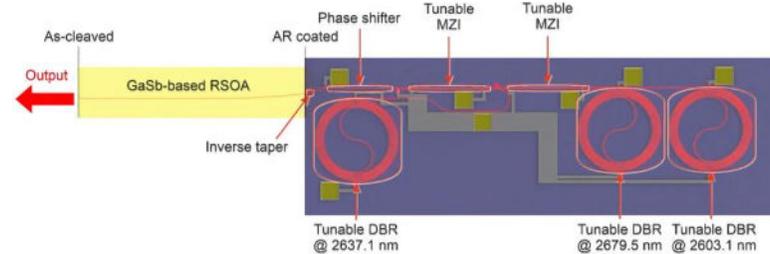
First published: 14 April 2023 | <https://doi.org/10.1002/lpor.202201028> | Citations: 1



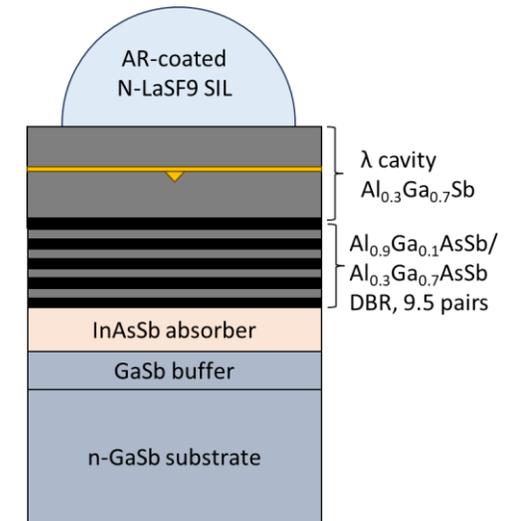
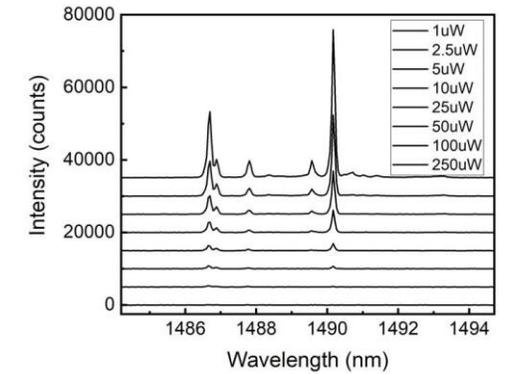
Discretely Tunable (2594, 2629, 2670 nm) GaSb/Si₃N₄ Hybrid Laser for Multiwavelength Spectroscopy

Samu-Pekka Ojanen , Jukka Viheriälä, Nouman Zia, Eero Koivusalo, Joonas Hillska, Heidi Tuorila, Mircea Guina

First published: 15 September 2023 | <https://doi.org/10.1002/lpor.202300492>



GaSb QD system @ 1.5 μm



Teemu Hakkarainen et al.

Current status (month 5/24)

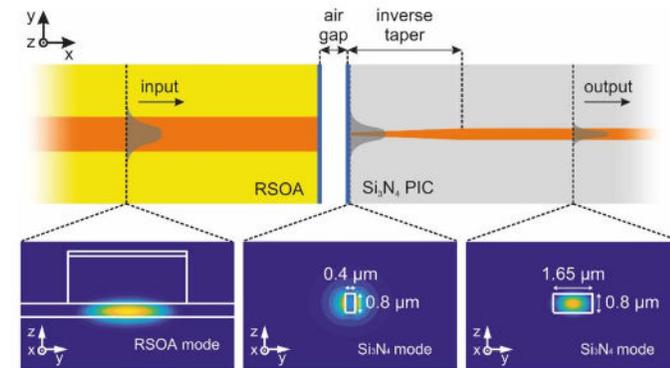
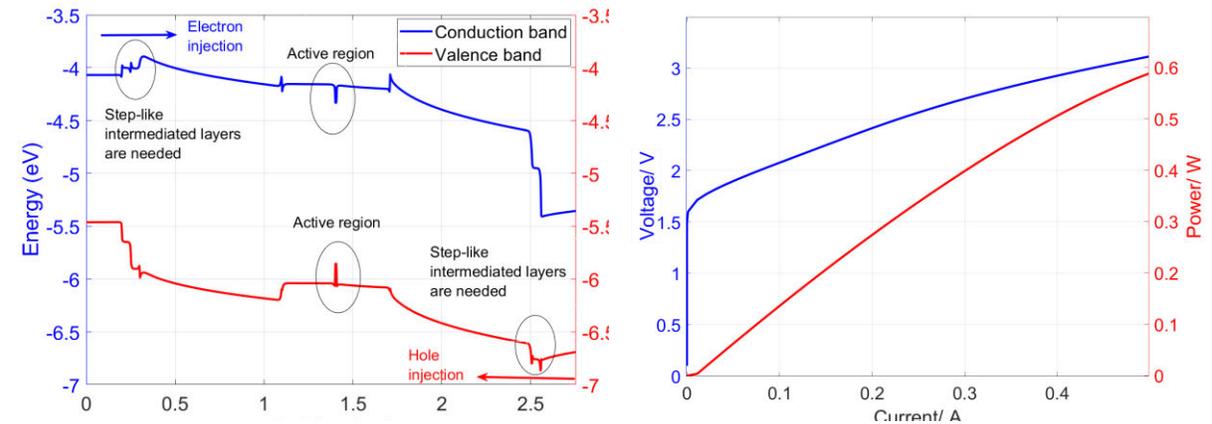
➤ Epi-structure

- Design ready for 780nm, 940nm
 - Selection of layer compositions for high modal gain and low loss, optimization of electrical characteristics
- 940 nm Epi to be grown early June

➤ PIC

- PIC/III-V interface design started
 - PIC platform selected
 - Selection of III-V WG and PIC-interface Circuit layouts to be started
- Plan to submit design to MPW run in Q4/2024

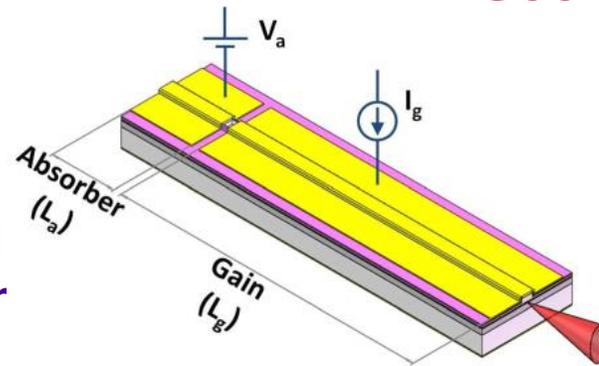
Simulation of 780 nm structure



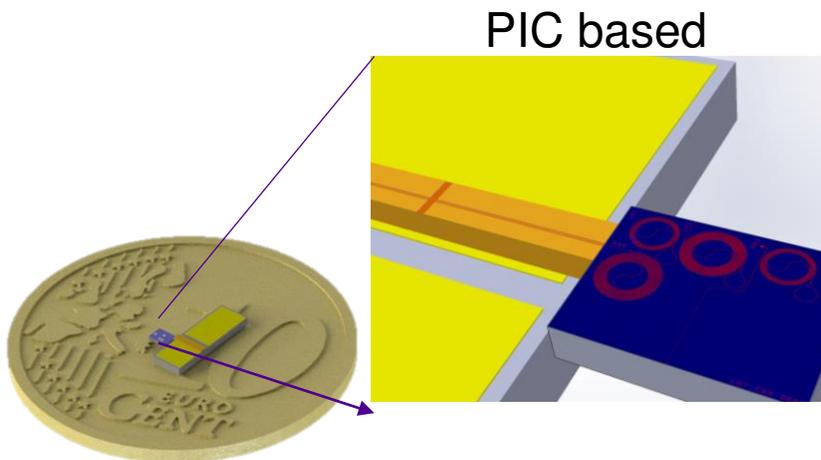
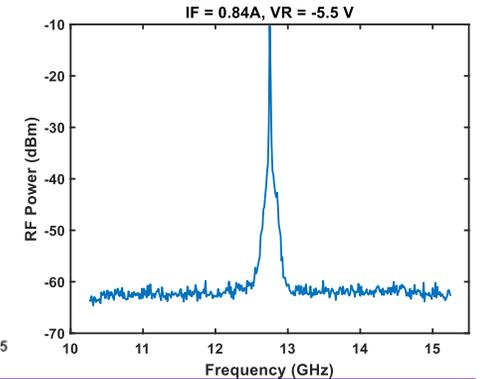
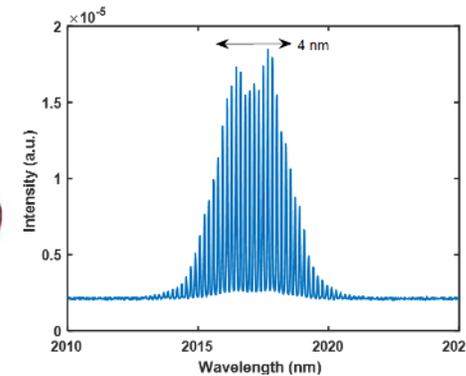
Connected activity: 2μm GaSb MLLD status

See presentation by Ajwaad Quashef

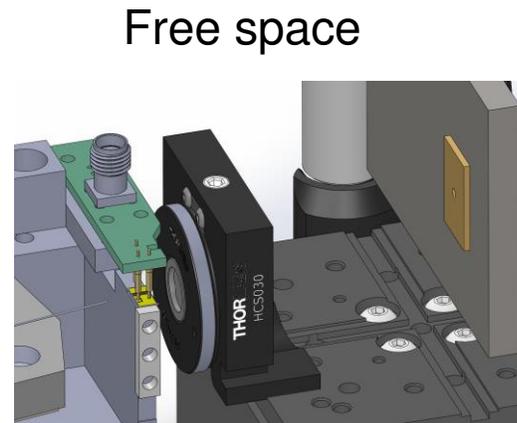
- Mode locking achieved using monolithic geometry
- Designs offering high isolation and reliability exhibits poor mode lockir
- Now AR coated chips are used in extended cavity configuration
 - With gold mirror in free space
 - With PIC delay line



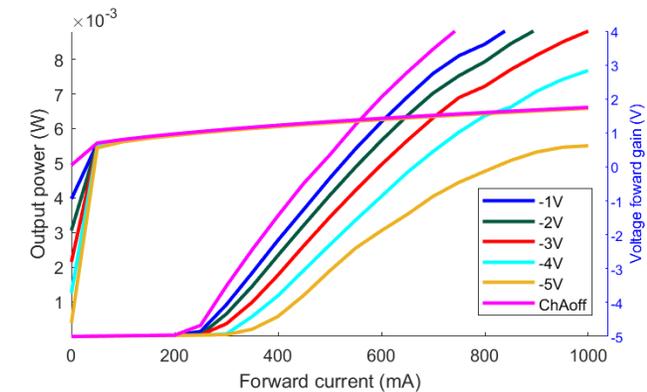
Monolithic
Extended cavity



PIC based



Free space

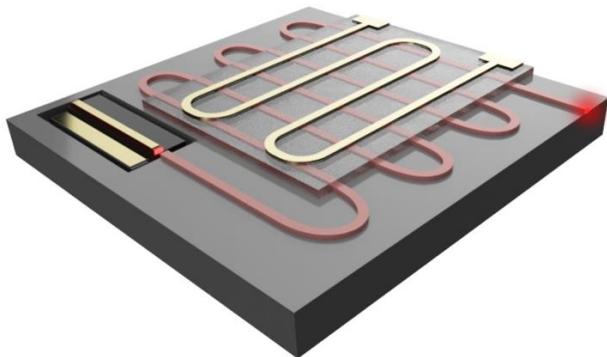


Roadmap to applications with GaSb QDs

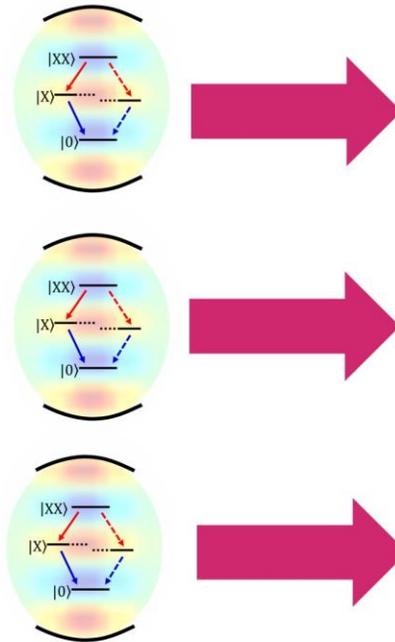
Photonic integration on Si-on-insulator (SOI)

On-chip routing of trigger laser

Integrated chip-based GHz pulsed trigger laser with wavelength tuning

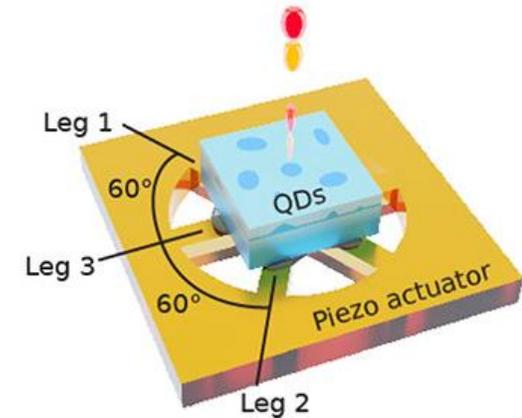


Arrays of QDs



Single-photon routing and manipulation on SOI

Entangled-photon sources at telecom wavelength



- **P-I-N gate** – charge stabilization
- **Piezo** – FSS elimination
- **Cavity** – emission enhancement and extraction efficiency

Collaborators



Prof. Peter Lodahl
Niels Bohr Institute



Prof. Armando Rasteli
Niels Bohr Institute

Research team

Dr. Teemu Hakkarainen
Dr. Jukka Viheriälä
Joonas Hilska
Patrik Rajala

Samu-Pekka Ojanen
Heidi Tuorila
Helmer Piirilä
Ajawaad Quashef

Funding



**Tampere Univ. Institute of
Advanced Study**



IntegrateQT
QuantSi
CryoLight

**BUSINESS
FINLAND**

QuTI

Thank you!

NEXT-GEN PACKAGING: EUROPEAN CHIPS ACT AND ADVANCES IN MICROELECTRONICS & PHOTONICS

IMAPS Nordic 2024 Conference and Exhibition on Microelectronics and Packaging

11th – 13th June 2024, #NordPac24

Time: 11.6.2024 at 14:00-17:30 (Finnish time)
Evening program 18:00-21:00 (Finnish time)

Place: Congress Centre Puistotorni, Hämeenpuisto 28, Tampere



Dr. Martin Letz, Schott
AG, Germany

Semiconductor
packaging using
structured glass panels
as platform



Executive Director Twan
Korthorst, Synopsys
Photonic IC Solutions

Scalable foundry
enablement for electronic
and photonic co-design



Dr. How Yuan Hwang,
Tyndall National Institute

Photonic Components
Integration – the common
ground with microelectronic
packaging.

Register here



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Workshop at NordPac:
Photonics-electronics integration and co-packaging.
From technology to applications.

The VTT logo consists of the letters 'VTT' in a white, bold, sans-serif font, centered within a solid orange square. The background of the slide is a repeating pattern of stylized, interlocking shapes in blue, orange, white, and black, creating a complex, geometric visual texture.

VTT

Broadband active hyperspectral sensing for black plastic

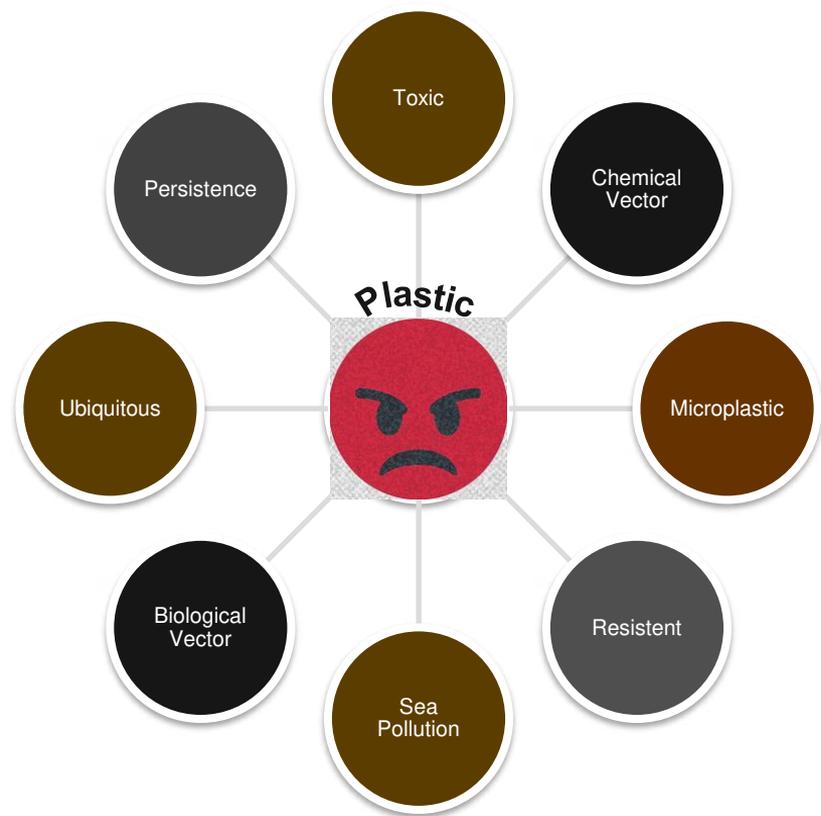
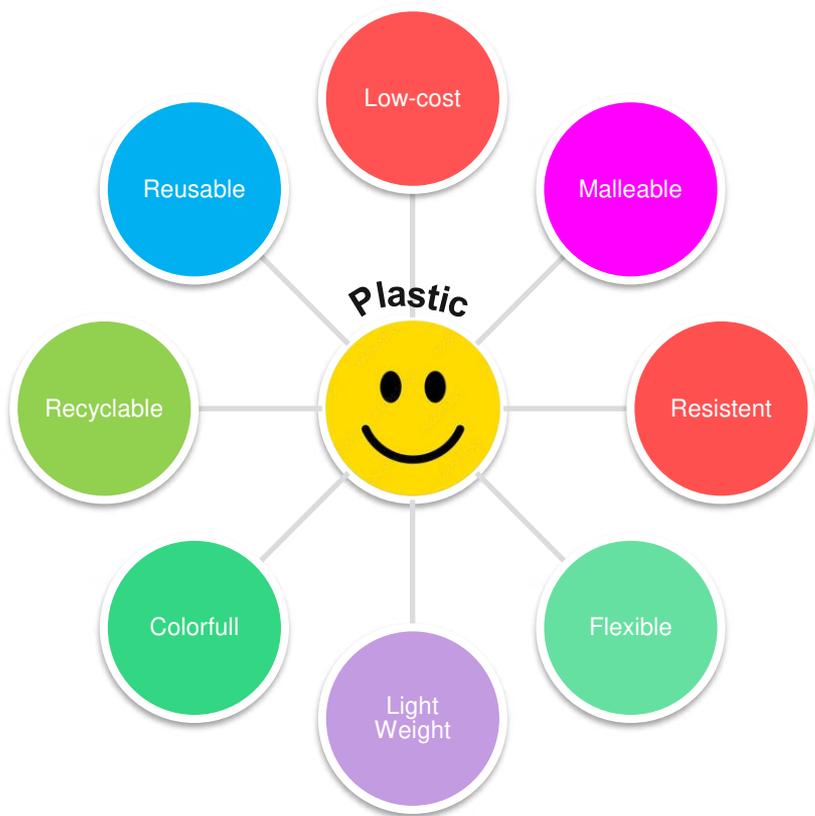
Eduardo Maia Paiva

7.6.2024

VTT – beyond the obvious

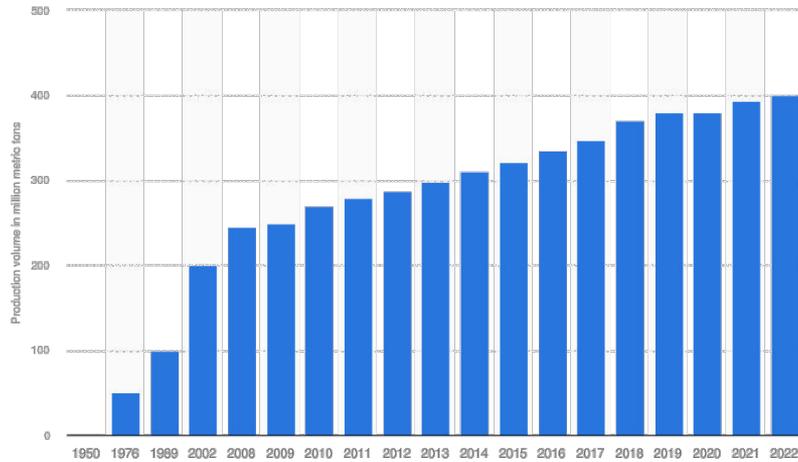
Plastic is a wonderful material!

Is it?



Plastic Management

Annual production of plastics worldwide from 1950 to 2022 (in million metric tons)



Sources
PlasticsEurope; Conversio; nova-institute
© Statista 2024

Additional information:
Worldwide; Conversio; nova-institute; 1950 to 2022; Estimates

How much plastic is recycled today?

Recycling rates vary by location, plastic type and application. Scientists estimate that only around 9 percent of all the plastic waste generated globally is recycled. Most of our plastic waste – a whopping 79 percent – ends up in landfills or in nature. Some 12 percent is incinerated.

Source: <https://stories.undp.org/why-arent-we-recycling-more-plastic#:~:text=Scientists%20estimate%20that%20only%20around,Some%2012%20percent%20is%20incinerated.>



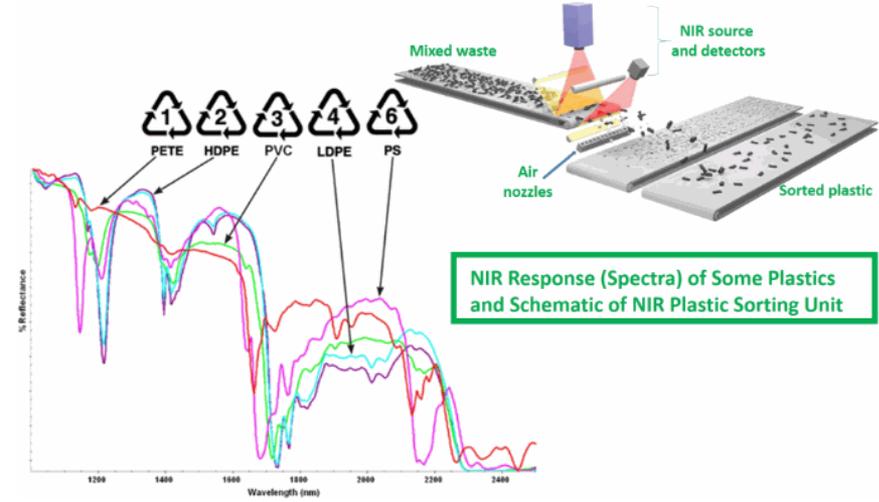
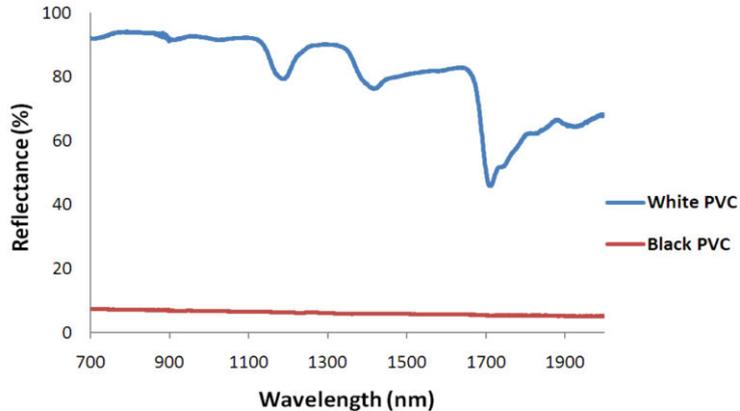
Plastic recycling: A big challenge!

- Plastics are several hundred different kinds of material that can be sorted by:
 - colours
 - shapes
 - chemical structure or a blend class
 - physical-chemical properties
 - commercial value
 - ...
- HIPS and ABS black plastic wastes:
 - are 55% of the Waste of Electric and Electrical Equipment (WEEE) stream.
 - Commercial interest
- Plastic sorting optical technologies
 - Near Infrared spectroscopy



Plastic sorting optical technologies

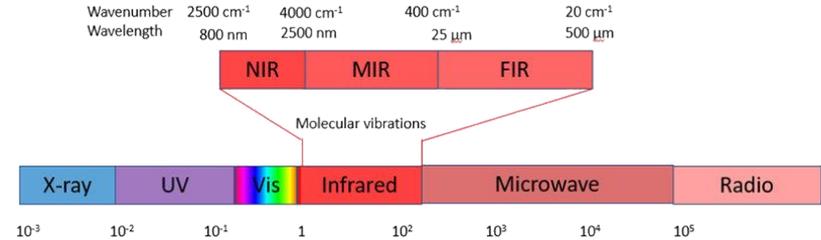
- Near Infrared hyperspectral imaging
 - Chemical identification and/or quantification
 - Fast, versatile, and adapted
 - Non-destructive
 - Relatively cheap
- However, it can not sort black plastic.
 - Carbon black absorbs all NIR light



<https://www.oceaninsight.com/blog/spectroscopy-for-plastics-recycling/>

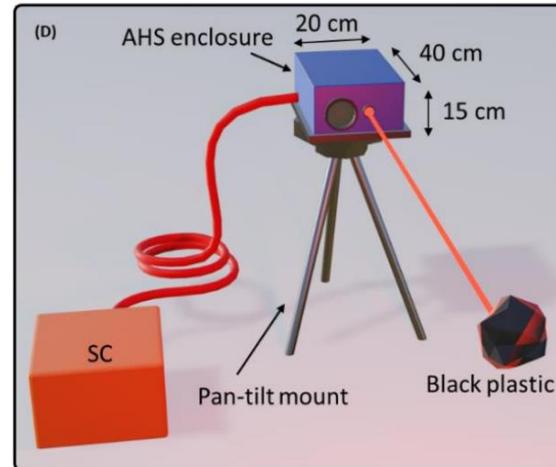
Plastic sorting optical technologies

- Mid-Infrared spectroscopy
 - It has the ability to sense black plastic



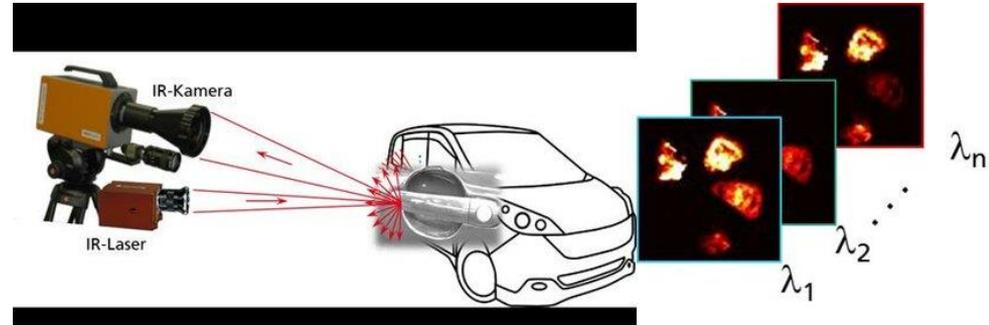
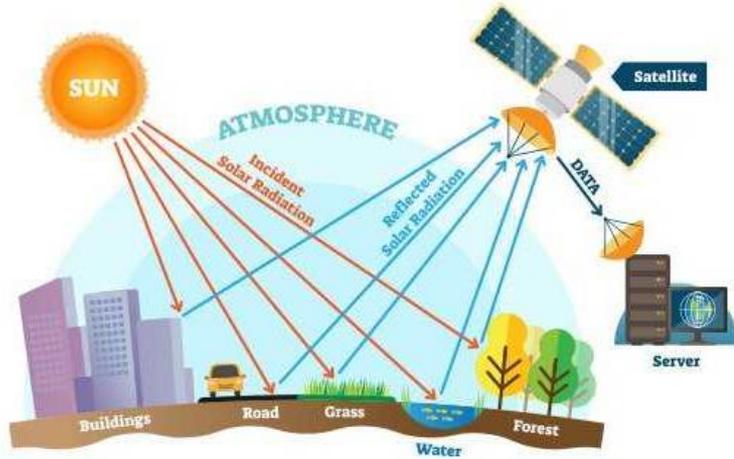
- However:
 - The traditional MIR spectroscopy (DRIFT and ATR) is limited by spectral acquisition rates.

- Solution:
 - Combining a broadband MIR light source with the VTT expertise in Active HyperSpectral (AHS) imaging technology.



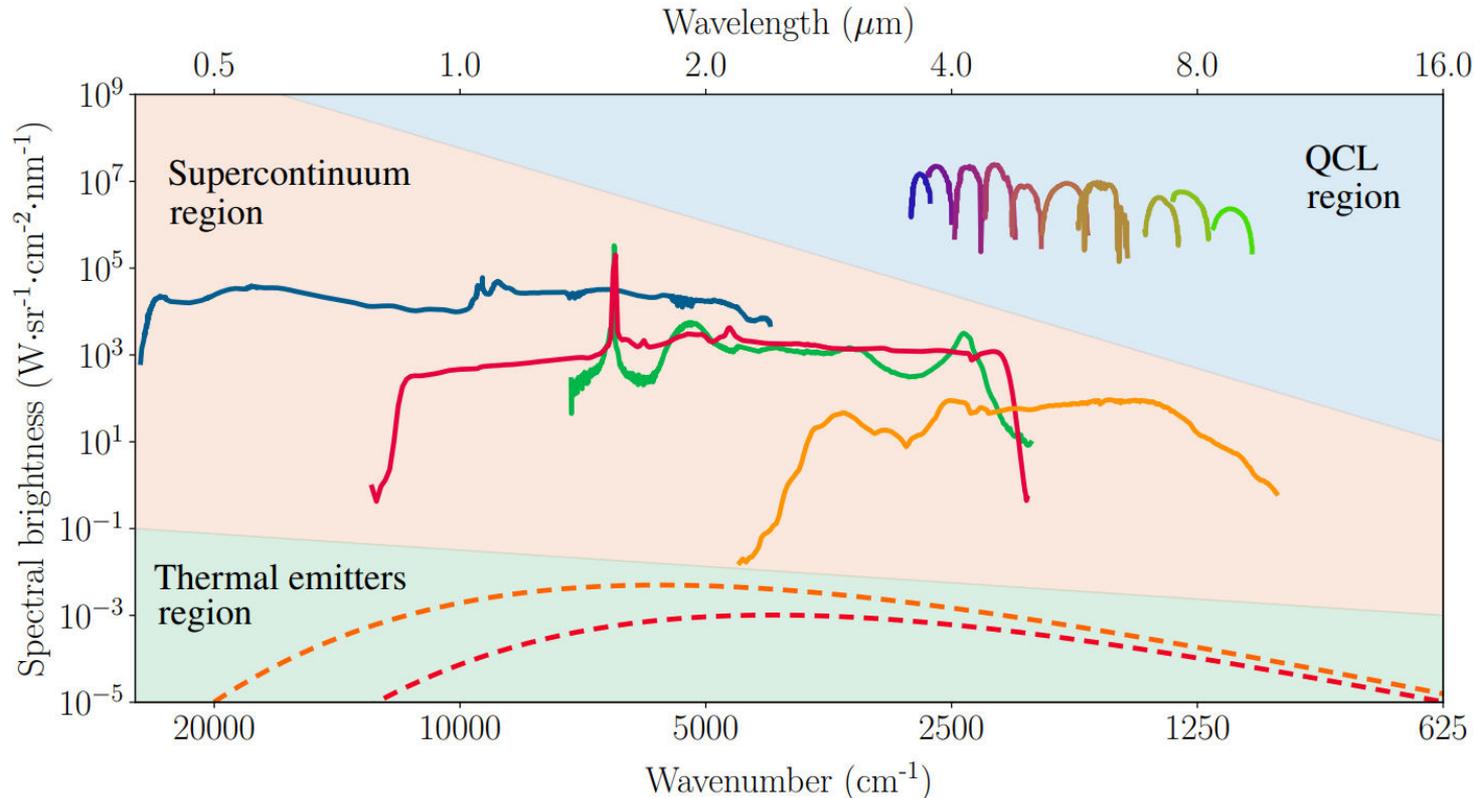
Active Hyperspectral – AHS

REMOTE SENSING



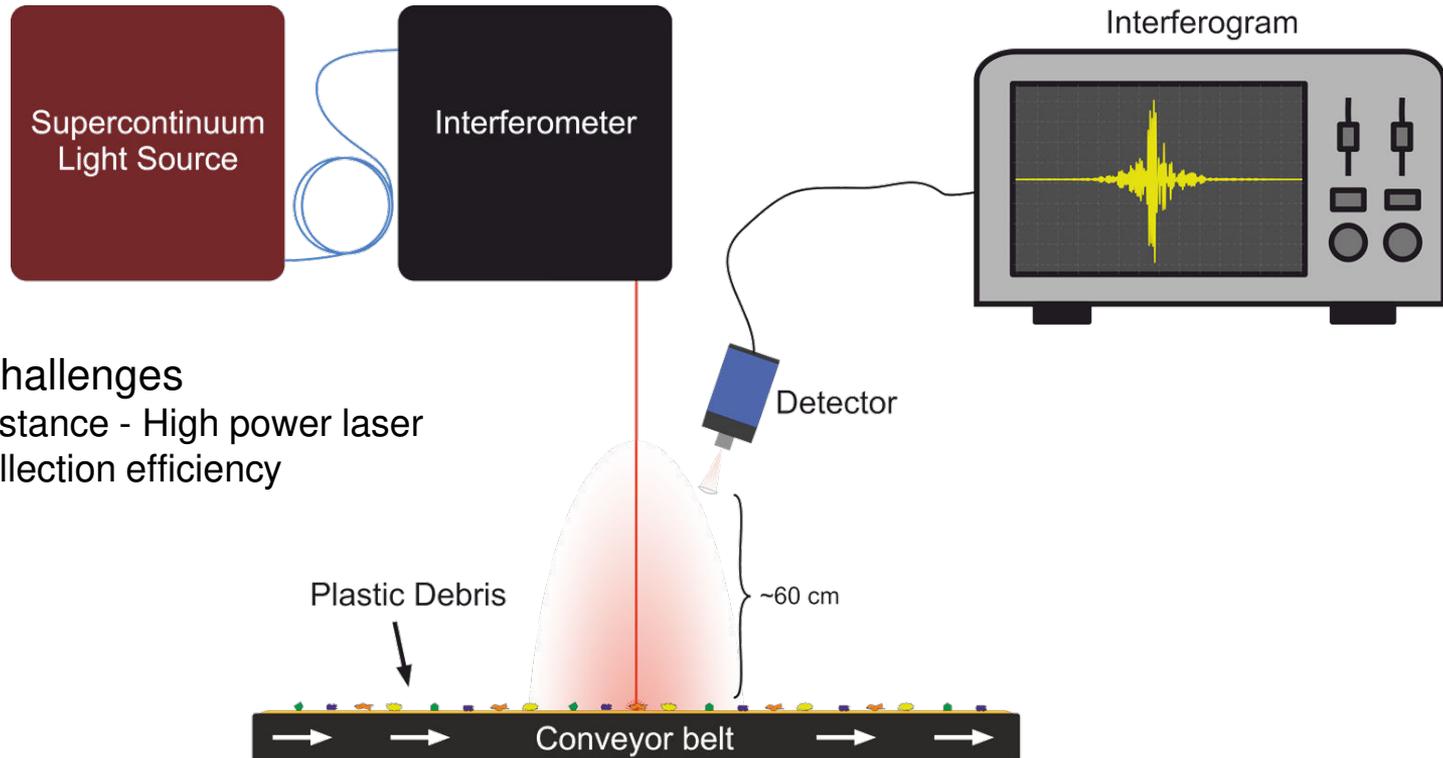
Supercontinuum Active Hyperspectral – SC-AHS

- The first challenge is to have a high-power broadband MIR light source.



Prototype - SC-AHS

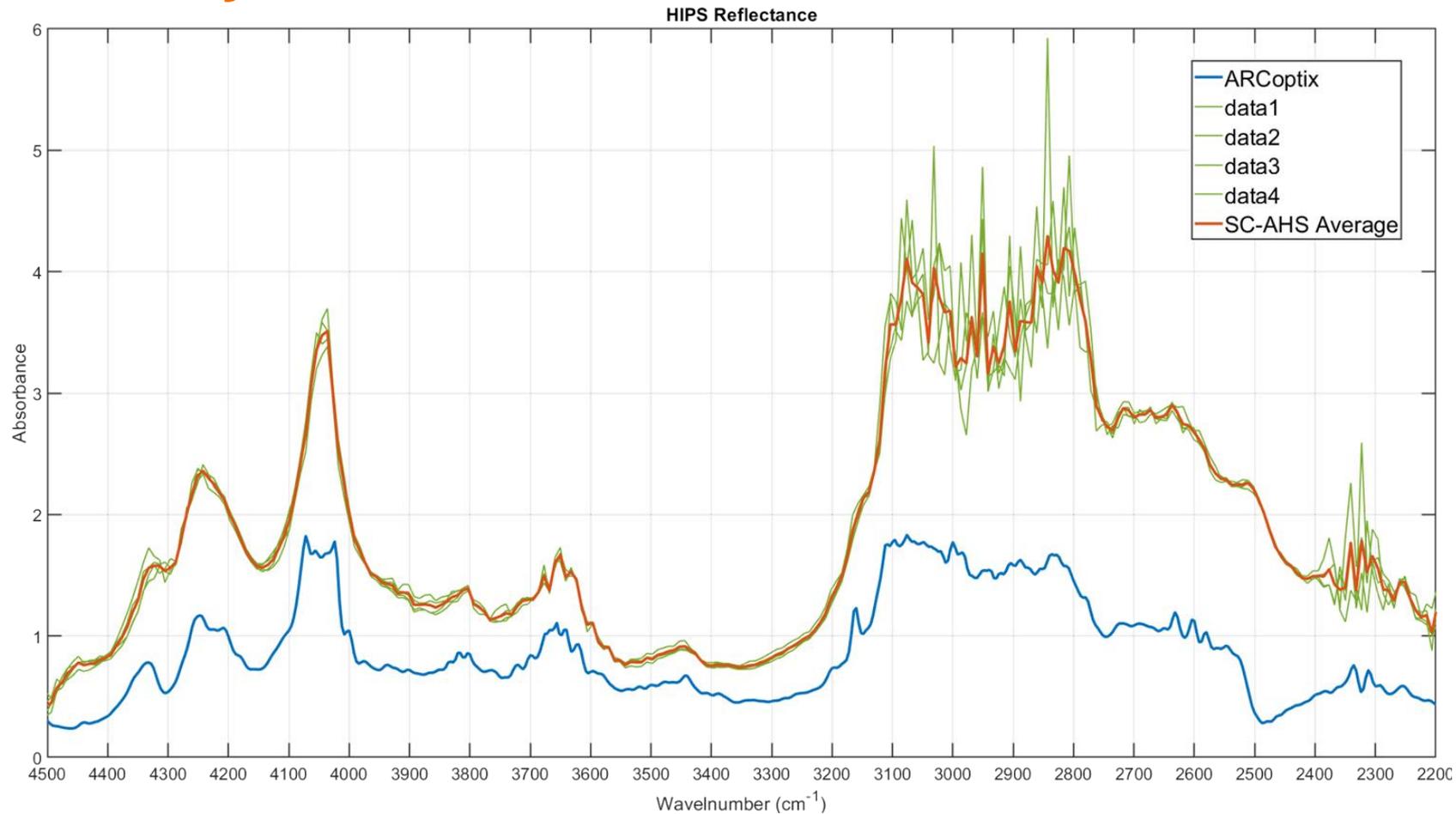
- The imaging is made by scanning laterally while conveyor belt rolling.



- **Critical points - Challenges**

- Measuring at a distance - High power laser
- Maximize light collection efficiency
- Fast scanning

Preliminary Results



Project Schedule



Project tasks & planned events	2024												2025											
	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18	19	20	21	22	23	24
Research tasks																								
T1	Development of benchtop system																							
T2	Evaluation of the benchtop system																							
T3	Modification of the setup for standoff detection																							
T4	Data collection - reference samples																							
T5	Data collection - waste samples																							
T6	Classification models for polymer identification																							
T7	Demonstration																							
Reporting and publications																								
Cooperation events																								
Workshop																							WS	
Visit																							V	
Final seminar																							S	
Dissemination																								
Conferences																							C1	C2

Implementation of interaction and impact

- **EU Horizon projects – NONTOX** - finalized
 - The NONTOX project successfully deployed an AHS prototype in a pilot recycling plant with SWERIM AB, sorting WEEE plastics by brominated flame-retardant content.
 - 1.95-2.45 μm spectral range
- **EU Horizon projects – PRIMUS** - ongoing
 - The EU PRIMUS project aims to develop and validate a method for assessing degradation in WEEE plastics using recycled plastic from CoolR
- **Current project**
 - Cover the gap in black plastic sorting in recycling plants.
 - Release an AHS prototype able to be tested at VTT's Polymer Pilot facility using a conveyor belt.

Implementation of interaction and impact

Societal and Environmental Impact:

- VTT focuses on improving recycled material quality and product value.
- Black plastics make up 15% of household plastic waste.
- Recycling challenges include hazardous substances like flame retardants.
- Current disposal methods mainly involve incineration.
- Recycling potential could reduce greenhouse gas emissions.
- Project technology aims to increase recycling rates by addressing sorting issues.
- Long-term impact expected upon implementation in recycling plants.
- Key performance indicator: Increase in recycled black plastic.

Economic Impact:

- Project outcomes focus on intellectual property rights and commercial potential.

bey⁰nd

the obvious

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